Important Note: Features and Supported Configurations will differ between the Z4 G4 Workstations with Intel® Xeon®W Processors and the Z4 G4 Workstation with Intel® Core™ X Processors. Where different – features are shown side by side. Supported configurations are indicated by the CPU Support references.

HP Z4 G4 Workstation



Front view

- 1. Front I/O module options
 - Premium (optional): power button, 2 USB 3.1 G1 Type-A, 2 USB 3.1 G2 Type-C™, Headset/Mic, SD Card Reader (optional) (Left-most Type-A port has charging capability)
 - Standard (shown here): power button, 4 USB 3.1 G1 Type-A (left-most Type-A port has charging capability), Headset audio, SD Card Reader (optional)
- 2. Front handle
- 3. 2 x 5.25" external drive bays



Intel® Xeon® W Processors



Intel® Core™ X-series Processors



Internal view

Intel® Xeon® W Processors

- 4. Intel® Xeon® Processors: W-2100 family
- 5. 2 PCle G3 x16, 2 PCle G3 x4, 1 PCle G3 x8
- 6. 2 PCIe G3 x4 M.2 for SSDs
- 7. 8 DIMM slots; DDR4-2666 ECC Registered RAM
- 8. PSU options:
 - 465W 90% efficient with 0 graphics power adapters
 - 750W 90% efficient with 2 graphics power adapters
 - 1000W 90% efficient with up to 4 graphics power Adapters

Intel® Core™ X-series Processors

- Intel® Core ™ i7-X-series processors Intel® Core ™ i9-X Series processors Intel® Core ™ i9 Extreme Edition processor
- 5. Core i9-X configs: 2 PCIe G3 x16, 2 PCIe G3 x4, 1 PCIe G3 x8 Core i7-X configs: 1 PCI G3 x16, 1 PCIe G3 x16 (x8 electrical), 2 PCIe G3 x4, 1 PCIe G3 x8 (mechanical only)
- 6. 1 PCIe G3 x4 M.2 for SSDs
- 7. 8 DIMM slots: DDR4-2666 Non-ECC Unbuffered RAM
- 8. PSU:
 - 1000W 90% efficient with up to 4 graphics power Adapters

9.	2 x 5.25" external drive bays
10.	2 x 2.5"/3.5" internal drive bays
11.	Front card guide and fan (select configurations)

6 x 6Gb/s SATA ports

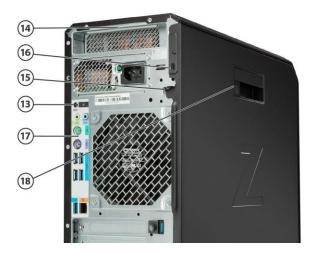
Intel® Xeon® W Processors

Intel® Core™ X-series Processors



12.





Rear view

Intel® Xeon® W Processors

Intel® Core™ X-series Processors

13. Rear power button
14. Rear handle
15. Padlock loop
16. Kensington lock slot
17. Rear I/O (top to bottom): 17. Rear I/O

- 17. Rear I/O (top to bottom):
 - Audio in/out,
 - Keyboard/Mouse PS/2 USB: 5 USB 3.1 G1 Type-A
 - 1x 1GbE port

USB: 6 USB 3.1 G1 Type-A
 2x 1GbE ports

Audio in/out,

Keyboard/Mouse PS/2

18.

Side panel barrel keylock (optional)

Overview

Overview

Form Factor Operating Systems

Minitower

Intel® Xeon® W Processors

Preinstalled:

- Windows 10 Pro 64 for Workstations
- HP Linux-ready (minimal OS ready for customer OS installation)
- Red Hat® Enterprise Linux® Desktop Workstation (Paper license with 1 year support; no preinstalled OS)

Supported:

- Windows 7 Professional 64-bit (downgrade media available by request from HP Support)*
- Red Hat® Enterprise Linux® Desktop 7.4
- SUSE Linux® Enterprise Desktop 12 SP3
- Ubuntu 16.04.3 LTS

Intel® Core™ X-series Processors

Preinstalled:

- Windows 10 Pro 64
- Windows 10 Pro 64 National Academic Plus
- HP Linux-ready (minimal OS ready for customer OS installation)
- Red Hat® Enterprise Linux® Desktop Workstation (Paper license with 1 year support; no preinstalled OS)

Supported:

- Red Hat® Enterprise Linux® Desktop 7.4
- SUSE Linux® Enterprise Desktop 12 SP3
- Ubuntu 16.04 LTS

Notes: For detailed OS/hardware support information for Linux®, see: http://www.hp.com/support/linux_hardware_matrix

*Windows 10 is preinstalled. Windows 7 media is only available upon request from HP Customer Support. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. For detailed OS hardware support information for Windows 7 on HP Z4 G4 see http://h10032.www1.hp.com/ctg/Manual/c05857891.pdf.

Available Processors

Name	Cores	Clock Speed (GHz)	Cache (MB)	Memory Speed (MT/s)	ECC memory support	Max memory support	Hyper- Threading	Featuring Intel® vPro™ Technology	Intel® Turbo Boost Technology 2.0 (GHz) ¹	Intel® Turbo Boost Max Technology 3.0 (GHz) ²	TDP (W)
	Intel® Xeon® W Processors										
Intel® Xeon® W-2195 processor	18	2.3	24.75	2666	YES	512GB	YES	YES	3.2, 4.3	N/A	140
Intel® Xeon® W-2175 processor	14	2.5	19.25	2666	YES	512GB	YES	YES	3.3, 4.3	N/A	140
Intel® Xeon® W-2155 processor	10	3.3	13.75	2666	YES	512GB	YES	YES	4.0, 4.5	N/A	140
Intel® Xeon® W-2145 processor	8	3.7	11.00	2666	YES	512GB	YES	YES	4.3, 4.5	N/A	140
Intel® Xeon® W-2135 processor	6	3.7	8.25	2666	YES	512GB	YES	YES	4.4, 4.5	N/A	140
Intel® Xeon® W-2133 processor	6	3.6	8.25	2666	YES	512GB	YES	YES	3.8, 3.9	N/A	140
Intel® Xeon® W-2125 processor	4	4.0	8.25	2666	YES	512GB	YES	YES	4.4, 4.5	N/A	120
Intel® Xeon® W-2123 processor	4	3.6	8.25	2666	YES	512GB	YES	YES	3.7, 3.9	N/A	120
Intel® Xeon® W-2104 processor	4	3.2	8.25	2400	YES	512GB	NO	YES	N/A	N/A	120



Intel® Xeon® W-2102 processor	4	2.9	8.25	2400	YES	512GB	NO	YES	N/A	N/A	120
	Intel® Core™ X-Series Processors										
Intel [®] Core™ i9-7980XE processor	18	2.6	24.75	2666	NO	128GB	YES	NO	4.2	4.4	165
Intel [®] Core™ i9-7960X processor	16	2.8	22.0	2666	NO	128GB	YES	NO	4.2	4.4	165
Intel [®] Core™ i9-7940X processor	14	3.1	19.25	2666	NO	128GB	YES	NO	4.3	4.4	165
Intel [®] Core™ i9-7920X processor	12	2.9	16.5	2666	NO	128GB	YES	NO	4.3	4.4	140
Intel [®] Core™ i9-7900X processor	10	3.3	13.75	2666	NO	128GB	YES	NO	4.3	4.5	140
Intel [®] Core™ i7-7820X processor	8	3.6	11.0	2666	NO	128GB	YES	NO	4.3	4.5	140
Intel [®] Core™ i7-7800X processor	6	3.5	8.25	2400	NO	128GB	YES	NO	4.0	N/A	140

¹For Intel [®] Xeon[®] W processors, the specifications shown in this column represent the following: all core maximum turbo frequency, single core maximum turbo frequency).

For Intel® Core™ processors, the specifications shown in this column refer to single core maximum turbo frequency.

Intel Turbo Boost Max Technology 3.0 identifies the best performing core(s) on a processor and provides increased performance on those cores by taking advantage of power and thermal headroom. Intel® Turbo Boost Max Technology 3.0 frequency is the clock frequency of the CPU when running in this mode.

NOTE: Processors that do not have certain turbo functionality are denoted as N/A.

Available Processors

Disclaimers

Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

Color Black **Convertibility** No

Expansion Slots (see more details)

Intel® Xeon® W Processors

Intel® Core™ X-series Processors

system board section for Slot 0: Mechanical-only, for use with devices that require only rear bulkhead mounting

Slot 1: PCI Express Gen3 x16 (from CPU)

Slot 2: PCI Express Gen3 x4 (from PCH) with open-ended connector*

Slot 3:

PCI Express Gen3 x16 (from CPU) Core i9-X configs: PCI Express Gen3 x16 (from

CPU)

Core i7-X configs: PCI Express Gen3 x16(mechanical) x8(electrical) (from CPU)

Slot 4: PCI Express Gen3 x4 (from PCH) with open-ended connector*

PCI Express Gen3 x8 (from CPU) with open-ended connector*

- Core i9-X configs: PCI Express Gen3 x8 (from CPU) with open-ended connector*



Overview

- Core i7-X configs: PCI Express Gen3 x8 (mechanical-only, no data) with open-ended connector*

M.2 Slot 1: M.2 PCIe Gen 3 x4 (from CPU) up to 80mm storage devices M.2 Slot 2: M.2 Slot 2:

M.2 PCIe Gen 3 x4 (from CPU) up to 80mm storage No 2nd M.2 connector/slot available

devices

* Open-ended connector allows a greater bandwidth (e.g. x16) card to be installed physically into a lower bandwidth connector/slot.

Expansion Bays (see storage section for more available. details)

2 internal 3.5" bays (with acoustic dampening drive carriers pre-installed). Optional 2.5" adapter

2 external 5.25" bays

3rd and 4th 3.5" HDD each occupy one external bay

3rd and 4th 2.5" HDD/SSD occupy a single external bay within a 2:1 carrier

Front I/O

Base: Power button, 1 Headset audio port, 4 USB 3.1 G1 Type A (1 charging)

Premium (optional): Power button with power/fault LED, Drive activity LED, 1 Headset audio

port, 2 USB 3.1 G1 Type-A (1 charging), 2 USB 3.1 G2 Type-C™

Optional: SD reader

Internal I/O 1 USB 3.1 G1 single-port header, 1 USB 2.0 single-port header and 1 USB 2.0 dual-port header

Rear I/O Intel® Xeon® W Processor Family Intel® Core™ X- Series Processor Family

> 6x USB 3.1 G1 Type-A 5x USB 3.1 G1 Type-A 2x 1GbE LAN ports (1x supporting Intel AMT) 1x 1GbE LAN ports

Audio: 1 Line out, 1 Line in (Line in can be retasked as microphone), 1 PS/2 mouse port, 1 PS/2

keyboard port, 1 Rear power button

Optional: 1 serial port (cable up to rear bulkhead)

Interfaces Supported SD card reader (optional)

6-channel SATA interface (6 @ 6.0 Gb/s)

6 channels are eSATA configurable for use with eSATA CTO/AMO Kit (No hot plug / hot swap

supported)

USB 2.0, USB 3.1 G1 (aka USB 3.0), USB 3.1 G2 (optional)

On-board RAID Support SATA RAID 0 Striped Array Configuration

> SATA RAID 1 Mirrored Array Configuration SATA RAID 10 Striped/Mirrored Configuration

Chassis Dimensions (H x

W x D) W: 6.65" (169mm)

D: 17.5" (445mm)

H: 15.2" (386mm)

Packaged Dimensions H: 22.5" (572mm)

> W: 12.4" (314mm) D: 22.2" (563mm)

Rack Dimensions

Weight Exact weights depend upon configuration (System weight only).

> Minimum: 10.2 kg (22.4 lbs.) Standard: 11.3 kg (24.9 lbs.) Maximum: 17.3 kg (38.2 lbs.)

Temperature Non-operating: -40° to 60° C (-40° to 140° F)



Overview

Operating: 5° to 35° C (40° to 95° F)

Above 1524 m (5,000 feet) altitude, the maximum operating temperature is reduced by 1° C (1.8° F)

for every 305 m (1,000 feet) increase in elevation

Maximum rate of change: 10 °C/hr No direct sustained sunlight

Operating: 10% to 85% relative humidity, non-condensing, 35° C maximum wet bulb Humidity

Non-operating: 10% to 90% relative humidity, non-condensing, 35° C maximum wet bulb

Maximum Altitude (nonpressurized)

Operating (with Rotational Hard Drives): 3.048 m (10,000 feet) Operating (with only Solid-State Drives): 5,000 m (16,404 feet)

Non-operating: 12,192 m (40,000 feet)

Maximum operating temperature is reduced as altitude increases. See Temperature for details.

Power Supply

Processor Support

XW

465 watts wide-ranging, active Power Factor Correction, 90% Efficient, with no 6-pin graphics power cables.

The Z4 G4 465W power supply efficiency report can be found at this link: https://plugloadsolutions.com/psu_reports/HP%20INC_DPS-465AB-3%20A_465W_ECOS%204939_Report.pdf

XW MID RANGE

ENTRY

750 watts wide-ranging, active Power Factor Correction, 90% Efficient, with 2x 6-pin graphics power cables.

The Z4 G4 750W power supply efficiency report can be found at this link: https://plugloadsolutions.com/psu/reports/HP%20INC DPS-750AB-36%20A_750W_ECOS%204938_Report.pdf

HIGH-END

XW, 1000 watts wide-ranging, active Power Factor Correction, 90% Efficient.

CX (i9) Includes 4x 6+2-pin graphics power cables: also includes a Front Fan and Card Guide kit to

CX (i7) enable support for dual high end graphics solutions.

Includes 2x 6-pin graphics power cables.

The Z4 G4 1000W power supply efficiency report can be found at this link:

https://plugloadsolutions.com/psu_reports/HP_D15-1K0P1A_1000W_EC0S%204838_Report.pdf

NOTE: 1000 W internal power supply, up to 90% efficiency, active PFC available the first half of 2018

Workstation ISV Certifications

See the latest list of certifications at

http://www8.hp.com/us/en/campaigns/workstations/industries-and-partners.html



Supported Components

Processors		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	Intel® Xeon® W-2100 Series CPU				
	Intel® Xeon® W-2195 2.3 2666 18C CPU	Υ	N		
	Intel® Xeon® W-2175 2.5 2666 14C CPU	Υ	N		
	Intel® Xeon® W-2155 3.3 2666 10C CPU	Υ	N		
	Intel® Xeon® W-2145 3.7 2666 8C CPU	Υ	N		
	Intel® Xeon® W-2135 3.7 2666 6C CPU	Υ	N		
	Intel® Xeon® W-2133 3.6 2666 6C CPU	Υ	N		
	Intel® Xeon® W-2125 4.0 2666 4C CPU	Υ	N		
	Intel® Xeon® W-2123 3.6 2666 4C CPU	Υ	N		
	Intel® Xeon® W-2104 3.2 2400 4C CPU	Υ	N		
	Intel® Xeon® W-2102 2.9 2400 4C CPU	Υ	N		
	Intel® Core™ X-Series CPU				
	Intel® Core™ i9-7980XE 2.6 2666 18C CPU	Υ	N		
	Intel® Core™ i9-7960X 2.8 2666 16C CPU	Υ	N		
	Intel® Core™ i9-7940X 3.1 2666 14C CPU	Υ	N		
	Intel® Core™ i9-7920X 2.9 2666 12C CPU	Υ	N		
	Intel® Core™ i9-7900X 3.3 2666 10C CPU	Υ	N		
	Intel® Core™ i7-7820X 3.6 2666 8C CPU	Υ	N		
	Intel® Core™ i7-7800X 3.5 2400 6C CPU	Υ	N		

Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

Monitors / Displays		Processor Supports	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP Z Display Z22n G2	XW, CX		Υ	1JS05AA	
	HP Z Display Z23n G2	XW, CX		Υ	1JS06AA	
	HP Z Display Z24i G2	XW, CX		Υ	1JS08AA	
	HP Z Display Z24n G2	XW, CX		Υ	1JS09AA	
	HP Z Display Z24nf G2	XW, CX		Υ	1JS07AA	
	HP Z Display Z27n G2	XW, CX		Υ	1JS10AA	
	HP Z Display Z27s (4K display)	XW, CX		Υ	J3G07AA	
	Supported by all operating systems av Screen size measured diagonally	ailable from HP				



Supported Components

Storage / Hard Drives*

SAS Hard Drives	SAS Hard Drives for HP Workstations	Processor Supports	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	SAS Hara Brives for the Workstations	Supports	configured		Maniber	Hotes
	HP 300GB 15k SAS SFF	XW	Υ	Υ	L5B74AA	

NOTE: Only available on Xeon W configs SAS controller add-in card required

*For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity may be less. Up to 32GB (for Windows 10) is reserved for system recovery software.

SATA Hard Drives		Processor Supports	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	SATA (Serial ATA) Hard Drives for HP Workstations					
	500GB SATA 7200RPM 6Gb/s 3.5" HDD	XW, CX	Υ	Υ	LQ036AA	
	500GB SATA 7200RPM 6Gb/s 0PAL2 SFF 3.5" HDD	XW, CX	Υ	Y	D8N29AA	
	1TB SATA 7200RPM 3.5" HDD	XW, CX	Υ	Υ	LQ037AA	
	1TB SATA 7200RPM Ent 3.5" HDD	XW, CX	Υ	Υ	WOR10AA	
	2TB SATA 7200RPM HDD	XW, CX	Υ	Υ	QB576AA	
	4TB SATA 7200RPM Ent 3.5" HDD	XW, CX	Υ	Υ	K4T76AA	
	6TB SATA 7200RPM Ent 3.3" HDD	XW, CX	Υ	Υ	3DH90AA	
	NOTES:					

Up to (4) 3.5-inch 7200 rpm SATA drives: 500 GB, 1.0, 2.0, 4.0, 16TB max total

SATA Solid State Drives		Processor Supports	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP Solid State Drives (SSDs) for Workstations					
	HP 256GB SATA SSD	XW, CX	Υ	Υ	A3D26AA	
	HP 512GB SATA SSD	XW, CX	Υ	Υ	D8F30AA	
	HP 1TB SATA SSD	XW, CX	Υ	Υ	F3C96AA	
	HP 2TB SATA SSD	XW, CX	Υ	Υ	Y6P08AA	
	HP 256GB SATA SED OPAL2 SSD	XW, CX	Υ	Υ	G7U67AA	
	HP 512GB SATA SED OPAL2 SSD	XW, CX	Υ	Υ	N8T26AA	
	HP 240GB SATA Enterprise SSD	XW, CX	Υ	Υ	T3U07AA	
	HP 480GB SATA Enterprise SSD	XW, CX	Υ	Y	T3U08AA	



Supported Components

PCIe Solid State

Drives

	Processor Supports	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
PCIe SSDs for HP Workstations					
HP Z Turbo Drive 256GB MLC Z4/Z6 G4 SSD Kit	XW, CX	Υ	Υ	1PD56AA	
HP Z Turbo Drive 512GB MLC Z4/Z6 G4 SSD Kit	XW, CX	Υ	Υ	1PD57AA/AT	
HP Z Turbo Drive 1TB MLC Z4/Z6 G4 SSD Kit	XW, CX	Υ	Υ	1PD58AA	
HP Z Turbo Drive 256GB TLC Z4/Z6 G4 SSD Kit	XW, CX	Υ	Υ	1PD59AA/AT	
HP Z Turbo Drive 512GB TLC Z4/Z6 G4 SSD Kit	XW, CX	Υ	Υ	1PD60AA	
HP Z Turbo Drive 1TB TLC Z4/Z6 G4 SSD Kit	XW, CX	Υ	Υ	1PD61AA	
HP Z Turbo Drive 256GB Z4/Z6 G4 SED Kit	XW, CX	Υ	Υ	TBD	
HP Z Turbo Drive 512GB Z4/Z6 G4 SED Kit	XW, CX	Υ	Υ	TBD	
HP Z Turbo Drive Quad Pro					
HP Z Turbo Drive Quad Pro 2x256GB PCIe® SSD	XW, CX (i9)	Υ	Υ	N2M98AA	1, 4
HP Z Turbo Drive Quad Pro 2x512GB PCIe® SSD	XW, CX (i9)	Υ	Υ	N2M99AA	1, 4
HP Z Turbo Drive Quad Pro 2x1TB PCIe® SSD	XW, CX (i9)	Υ	Υ	Т9Н99АА	1, 4
HP Z Turbo Drive Quad Pro 256GB SSD module	XW, CX (i9)	N	Υ	N2N00AA	1, 3, 4
HP Z Turbo Drive Quad Pro 512GB SSD module	XW, CX (i9)	N	Υ	N2N01AA	1, 3, 4
HP Z Turbo Drive Quad Pro 1TB SSD module	XW, CX (i9)	N	Υ	T9J00AA	1, 3, 4

Note 1: All HP Z Turbo Drive Quad Pro modules require the Z4 G4 Fan & Front Card Kit, available as CTO (1MY89AV) and AMO (1XM33AA)

Note 3: M.2 SSD module only, designed to be installed into the Z Turbo Drive Quad Pro carrier **Note 4:** Z Turbo Drive Quad Pro is not supported on Core i7-X configurations

Hard Drive Controllers	_				Option Kit		
		Processor Supports	Factory Configured	Option Kit	Part Number	Support Notes	
	SAS Controller						
	MicroSemi SmartHBA2100-4i4e SAS Controller NOTE: Only available on Xeon W configurations	XW	Y	Υ	1FV90AA		

Graphics

	Processor Supports	Factory Configured	Option Kit	Option Kit Part Number	Support Notes	Supported # of cards
Graphics Cable Adapters						
HP DisplayPort to HDMI Adapter	XW, CX	Υ	Υ	K2K92AA		
HP DisplayPort to Dual Link DVI Adapter	XW, CX	Υ	Υ	NR078AA		
HP DisplayPort to DVI-D Adapter	XW, CX	Υ	Υ	FH973AA		
HP DisplayPort to DVI-D Adapter (2-pack)	XW, CX	Υ	N			
HP DisplayPort to DVI-D Adapter (4-pack)	XW, CX	Υ	N			
HP DisplayPort to DVI-D Adapter (6-pack)	XW, CX	Υ	N			
HP miniDP-to-DP Adapter	XW, CX	Υ	Υ	2MY05AA		



Supported Components

HP miniDP-to-DP Adapter (2-pack)	XW, CX	Υ	N			
HP miniDP-to-DP Adapter (4-pack)	XW, CX	Υ	N			
HP miniDP-to-DP Adapter (8-pack)	XW, CX	Υ	N			
NVIDIA SLI 2-slot Graphics Connector	XW, CX	Υ	Υ	2YY84AA		
Entry 3D						
NVIDIA® Quadro® P400 2GB Graphics	XW, CX	Υ	Υ	1ME43AA/AT	4	2
NVIDIA® Quadro® P600 1st GFX 2GB Graphics	XW, CX	Υ	Υ	1ME42AA/AT	4	2
NVIDIA® Quadro® P620 2GB Graphics	XW, CX	Υ	Υ	TBD	4	2
AMD FirePro™ W2100 2GB Graphics	XW, CX	Υ	Υ	J3G91AA/AT	3	2
Mid-range 3D						
NVIDIA® Quadro® P1000 1st GFX 4GB Graphics	XW, CX	Υ	Υ	1ME01AA/AT	3, 4	2
NVIDIA® Quadro® P2000 1st GFX 5GB Graphics	XW, CX	Υ	Υ	1ME41AA/AT	3, 4	2
AMD Radeon™ Pro WX 3100 4GB Graphics	XW, CX	Υ	Υ	2TF08AA	3, 4	2
AMD Radeon™ Pro WX 4100 4GB Graphics	XW, CX	N	Υ	ZOB15AA/AT	3, 4	2
High End 3D						
NVIDIA® Quadro® P4000 1st GFX 8GB Graphics	XW, CX	Υ	Υ	1ME40AA/AT	1, 2	2
NVIDIA® Quadro® P5000 1st GFX 16GB Graphics	XW, CX	Υ	Υ	ZOB13AA/AT	1, 2, 5	2
NVIDIA® Quadro® P6000 1st GFX 24GB Graphics	XW, CX	Υ	Υ	ZOB12AA/AT	1, 2, 5	2
NVIDIA® Quadro® GP100 16GB Graphics	XW, CX	Υ		TBD	1, 2, 5	2
AMD Radeon™ Pro WX 7100 1st GFX 8GB Graphics	XW, CX	Υ	Υ	ZOB14AA/AT	1, 2	2
AMD Radeon™ Pro WX 9100 16GB Graphics	XW, CX	Υ		TBD	1, 2, 5	2
NVIDIA® Quadro® Sync II	XW, CX	Υ	Υ	1WT20AA		

NOTE 1: Single graphics configuration requires the HP Z4 G4 Fan and Front Card Guide Kit, which is available both CTO (1MY89AV) and AMO (1XM33AA).

NOTE 2: Single graphics configuration requires the 750W chassis or 1000W chassis.

NOTE 3: Dual graphics configuration requires the HP Z4 G4 Fan and Front Card Guide Kit, which is available both CTO (1MY89AV) and AMO (1XM33AA).

NOTE 4: Dual graphics configuration requires the 750W chassis or 1000W chassis.

NOTE 5: Dual graphics configuration requires the 1000W chassis.

Memory	СТО	Processor Supports	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	DDR4-2666 ECC Registered DIMMs					
	HP 8GB (1x8GB) DDR4-2666 ECC Reg RAM	XW	Υ	Υ	1XD84AA/AT	1
	HP 16GB (2x8GB) DDR4-2666 ECC Reg RAM	XW	Υ			1
	HP 24GB (3x8GB) DDR4-2666 ECC Reg RAM	XW	Υ			1
	32GB (4x8GB) DDR4-2666 ECC Reg RAM	XW	Υ			1
	64GB (8x8GB) DDR4-2666 ECC Reg RAM	XW	Υ			1
	16GB (1x16GB) DDR4-2666 ECC Reg RAM	XW	Υ	Υ	1XD85AA/AT	1
	32GB (2x16GB) DDR4-2666 ECC Reg RAM	XW	Υ			1
	64GB (4x16GB) DDR4-2666 ECC Reg RAM	XW	Υ			1
	128GB (8x16GB) DDR4-2666 ECC Reg RAM	XW	Υ			1



Supported Components

32GB (1x32GB) DDR4-2666 ECC Reg RAM	XW	N	Υ	1XD86AA/AT	1, 2
64GB (2x32GB) DDR4-2666 ECC Reg RAM	XW	Υ			1, 2
128GB (4x32GB) DDR4-2666 ECC Reg RAM	XW	Υ			1, 2
256GB (8x32GB) DDR4-2666 ECC Reg RAM	XW	Υ			1, 2
HP 8GB (1x8GB) DDR4-2666 nECC RAM	CX	Υ	Υ	3PL81AA	1
HP 16GB (2x8GB) DDR4-2666 nECC RAM	CX	Υ			1
HP 32GB (4x8GB) DDR4-2666 nECC RAM	CX	Υ			1
HP 64GB (8x8GB) DDR4-2666 nECC RAM	CX	Υ			1
HP 16GB (1x16GB) DDR4-2666 nECC RAM	CX	Υ	Υ	3PL82AA	1
HP 32GB (2x16GB) DDR4-2666 nECC RAM	CX	Υ			1
HP 64GB (4x16GB) DDR4-2666 nECC RAM	CX	Υ			1
HP 128GB (8x16GB) DDR4-2666 nECC RAM	CX	Υ			1

NOTES:

For details on the supported memory configurations on the HP Z4 G4 Workstation, please refer to the System Technical Specifications - System Board section of this document.

Each processor supports up to 4 channels of DDR4 memory. To realize full performance at least 1 DIMM must be inserted into each channel.

The CPUs determine the speed at which the memory is clocked. If an 2400MT/s capable CPU is used in the system, the maximum speed the memory will run at is 2400MT/s, regardless of the specified speed of the memory.

NOTE 1: ONLY DDR4 DIMMs are supported.

NOTE 2 Memory configurations using 32GB DIMMs require the HP Z4 Memory Cooling Solution, which is available both CTO (1MY90AV) and AMO (1XM34AA).

Multimedia and Audio Devices



0-1:-- V:1

Supported Components

Multimedia and Audio Devices

	Processor Supports	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
Integrated Realtek HD ALC221 Audio	XW, CX	Υ	N		

Optical and Removable Storage

			Uption Kit		
Processor Supports	Factory Configured	Option Kit	Part Number	Support Notes	
XW, CX	Υ	Υ	K3R65AA	1	
XW, CX	Υ	Υ	K3R63AA	1	
XW, CX	Υ	Υ	K3R64AA	1	
XW, CX	Υ	Υ	YOL99AA		
	XW, CX XW, CX XW, CX XW, CX	XW, CX Y XW, CX Y XW, CX Y XW, CX Y	Supports Configured Kit XW, CX Y Y XW, CX Y Y XW, CX Y Y XW, CX Y Y	Processor Supports Configured Configured Kit Number XW, CX Y Y K3R65AA XW, CX Y Y K3R63AA XW, CX Y Y K3R64AA	

NOTE 1: Installing an optical drive into Z4 G4 requires a 5.25" external bay adapter (Option Kit Part number NQ099A).

*Actual speeds may vary. No support for DVD-RAM (DVD Writer). Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.

With Blu-ray, certain disc, digital connection, compatibility and/or performance issues may arise, and do not constitute defects in the product. Flawless playback on all systems is not guaranteed. In order for some Blu-ray titles to play, they may require a DVI or HDMI digital connection and your display may require HDCP support. HD-DVD movies cannot be played on this workstation.

Networking and Communications

	Processor Supports	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
Intel® i350-T2 PCIe Dual Port Gigabit NIC	XW, CX	Υ	Υ	V4A91AA	
Intel® i350-T4 PCIe 4-Port Gigabit NIC	XW, CX	N	Υ	W8X25AA	
Intel® Ethernet I210-T1 PCIe x1 Gb NIC	XW, CX	Υ	Υ	E0X95AA	
Aquantia® AQN-108 Single-Port 5GbE NIC	XW, CX	N	Υ	1PM63AA	
Intel® X550-T2 10GbE Dual Port NIC	XW, CX	Υ	Υ	1QL46AA	
Intel® X710-DA2 10GbE SFP+ Dual Port NIC	XW, CX	Υ	Υ	1QL47AA	
HP 10GbE SFP+ SR Transceiver	XW, CX	Υ	Υ	C3N53AA	
Intel 8265 802.11 a/b/g/n/ac + BT PCIe WLAN	XW, CX	N	Υ	1QL48AA	

Racking and Physical Security



Supported Components

Racking and Physical Security

	Processor Supports	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP Z4/Z6 Side Panel Barrel Keylock	XW, CX	Υ	N		
HP Solenoid Lock / Hood Sensor	XW, CX	Υ	N		
HP Z4/Z6 Depth Adjustable Fixed Rail Rack Kit	XW, CX	N	Υ	2HW42AA	
HP Keyed Cable Lock 10mm	XW, CX	N	Υ	T1A62AA	

Input Devices

	Processor Supports	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
HP Wireless Business Slim Keyboard and Mouse	XW, CX	Υ	Υ	N3R88AA	
Business Slim PS/2 Wired Keyboard	XW, CX	Υ	Υ	N3R86AA	
USB Business Slim Wired Keyboard	XW, CX	Υ	Υ	N3R87AA	
USB Premium Wired Keyboard	XW, CX	Υ	Υ	Z9N40AA	
USB Wired SmartCard CCID Keyboard	XW, CX	Υ	Υ	E6D77AA	
3Dconnexion CADMouse	XW, CX	Υ	Υ	M5C35AA	
HP Optical USB Mouse	XW, CX	Υ	Υ	QY777AA	
HP PS/2 Mouse	XW, CX	Υ	Υ	QY775AA	
HP USB Hardened Mouse	XW, CX	Υ	Υ	P1N77AA	

Other Hardware

			Option Kit	
Processor Supports	Factory Configured	Option Kit	Part Number	Support Notes
XW, CX	Υ			
XW, CX	Υ	Υ	1XM32AA	
XW, CX	Υ	Υ	1XM34AA	Note 1
XW, CX	Υ	Υ	1XM33AA	Note 2
XW, CX	N	Υ	EM165AA	Note 3
XW, CX	Υ	Υ	GM110AA	
XW, CX	Υ	Υ	PA716A	
XW, CX	Υ			
	Supports XW, CX	Supports Configured XW, CX Y XW, CX Y	Supports Configured Kit XW, CX Y XW, CX Y Y XW, CX Y Y XW, CX Y Y XW, CX N Y XW, CX Y Y XW, CX Y Y XW, CX Y Y	Processor Supports Factory Configured Option Kit Part Number XW, CX Y Y 1XM32AA XW, CX Y Y 1XM32AA XW, CX Y Y 1XM34AA XW, CX Y Y 1XM33AA XW, CX N Y EM165AA XW, CX Y Y GM110AA XW, CX Y Y PA716A

Note 1: The HP Z4 G4 Memory Cooling Solution is available to add to any configuration for improved system cooling, but is required for memory configurations using 32GB DIMMs.

Note 2: Fan and Front Card Guide required with the following components:

- Specific graphics configurations (see Graphics section above)
- Any HP Z Turbo Quad Pro configuration

Note 3: The HP Internal USB Port kit has a single USB 2.0 type A connector.



Supported Components

Software		Processor Supports	Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	Sobey Video Editing SW	XW, CX	Υ	N		China only
	SW HP RGS for Z	XW, CX	Υ	N		



Supported Components

0

Operating Systems		Processor Supports	Support Notes
	Windows 10 Pro 64 for Workstations	XW	Note 1
	Windows 10 Pro 64	CX	Note 2
	Win 10 Pro 64 StF MSNA Plus	CX	Note 2
	Windows 7 Professional 64-bit	XW	Note 3, 4
	HP Linux® Ready	XW, CX	Note 5
	Red Hat® Enterprise Linux® (RHEL) Workstation - Paper License (1yr)	XW, CX	Note 6

NOTE 1: Only applicable to Xeon W configurations

NOTE 2: Only applicable to Core X configurations

NOTE 3: downgrade media available by request from HP Support. Not supported or available for Core X configurations.

NOTE 4: Windows 10 is preinstalled. Windows 7 media is only available for Xeon W configurations, upon request from HP Customer Support. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version **NOTE 5:** includes drivers for 64-bit OS versions of RHEL 6 & 7, SUSE Linux® Enterprise Desktop 11 and Ubuntu 14.04.

NOTE 6: This second OS must be ordered with the HP Linux® Installer Kit as the first OS.



System Technical Specifications

System Board

System Board Form Main System Board: **Factor** 27.7 x 28.0 cm 10.9 x 11.0 inches

Processor Socket Single LGA2066 R4

Chipset Intel® Xeon® W Processor Family Intel® Core™ X-series Processors

> Intel® C422 Chipset Intel® X299 chipset

Nuvoton NPCD315HA0DX (SIO-15) Super I/O Controller **Memory Expansion** 8 DDR4 memory slots Slots

Memory Type

DDR4, RDIMM (Registered), ECC: 8GB, 16GB and DDR4, UDIMM, non-ECC: 8GB and 16GB

Supported 32GB

Memory Modes Channel Interleaved **Memory Speed** 2666MT/s, 2400MT/s, and 2133MT/s

Memory Protection ECC available on data, parity on address and N/A

command

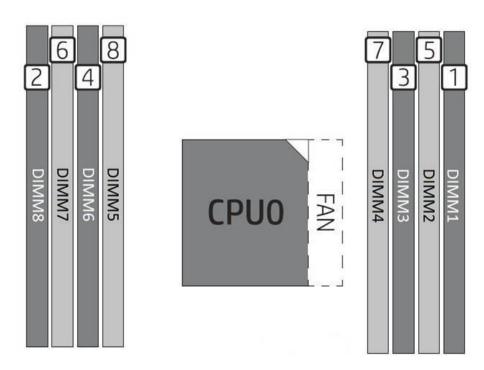
Maximum Memory Supports up to 256GB Supports up to 128GB

Memory Configuration (Supported) **Memory Load Order**

Supported

Only Registered DIMMs are supported.

Only non-ECC unbuffered DIMMs are supported



Note on Maximum Memory

Maximum memory capacities assume 64-bit operating systems such as Windows 10 Pro 64-bit, Windows 7 Professional 64-bit.



System Technical Specifications

PCI Express Connectors

Intel® Xeon® W Processor Family

Intel® Core™ X-series Processors

Slot 1 (top): PCI Express Gen3 x16 supplied by CPU.

Slot 2 (PCH): PCI Express Gen3 x4 supplied by PCH with open-ended connector. **

Slot 3:

Slot 3:

PCI Express Gen3 x16 supplied by CPU

Core i9-X configs: PCI Express Gen3 x16 supplied by

CPU

Core i7-X configs: PCI Express Gen3 x16 (mechanical)/ x8 (electrical)supplied by CPU

Slot 4 (PCH): PCI Express Gen3 x4 supplied by PCH with open-ended connector**

Slot 5:

Slot 5:

PCI Express Gen3 x8 supplied by CPU with openended connector** Core i9-X configs: PCI Express Gen3 x8 supplied by CPU with open-ended connector**
 Core i7-X configs: PCI Express Gen3 x8 (mechanical-only, no data) with open-ended

connector**

NOTE: Slots 1 through 5 support full-height, full-length cards (with extender)

M.2 Slot 1: PCI Express Gen3 x4 supplied by CPU

Socket Type 3, Key M, H4.2, sizes 2260-D5-M, 2280-D5-M, 22110-D5-M

M.2 Slot 2:

M.2 Slot 2:

PCI Express Gen3 x4 supplied by CPU Socket Type 3, Key M, H4.2, sizes 2260-D5-M, 2280-D5-M. 22110-D5-M No 2nd M.2 connector/slot available

** Open-ended connector allows a greater bandwidth (e.g. x16) card to be installed physically into a lower bandwidth connector/slot.



System Technical Specifications

Supported Drive Interfaces SATA

6 SATA @6Gb/s, supports RAID 0,1, 5, and 10 Factory integrated RAID is Microsoft Windows only

Serial Attached SCSI Intel® Xeon® W Processor Family

Intel® Core™ X-series Processors

Requires Optional PCIe card

not supported

Factory Configured RAID

RAID 0 configuration - striped array
 RAID 1 configuration - mirrored array
 RAID 10 striped and mirrored array

*HW RAID functionality not supported by Linux®. Use SW RAID functionality provided in the Red Hat® Operating system instead.

Integrated Graphics

No

Network Controller Intel® Xeon® W Processor Family

Intel® Core™ X-series Processors

Intel® I219-LM PCIe GbE LAN Intel® I210-AT PCIe® GbE LAN

Intel® I219-V PCIe GbE LAN
Supports the following management functionalities:

Supports the following management functionalities:

WOL and PXE 2.1

Intel AMT11.1, TXT, DASH 1.1, WOL, VLAN, Teaming

and PXE 2.1

External SATA (eSATA)

Supported on all SATA ports configurable with optional eSATA* cable kit

* hot plug / hot swap not supported with eSATA

IDE connector No

Floppy connector No

Serial 1 internal header

2nd SerialNoParallelNoAUX IN (audio)No

IEEE 1394 Connector(s)

Front None

Rear None

Internal None

USB Connector(s)

Front Front USB depends on which FIO module is selected:

- Standard: 4 USB 3.1 G1 Type A (1 charging)

- Premium: 2 USB 3.1 G2 Type C[™], 2 USB 3.1 G1 Type A (1 charging)

Rear Intel® Xeon® W Processor Family Intel® Core™ X-series Processors

6 USB 3.1 G1 Type A 5 USB 3.1 G1 Type-A

Internal 1 USB 3.1 G1 single-port header 1 USB 2.0 single-port header

1x USB 2.0 dual-port header



System Technical Specifications

HD Integrated Audio Realtek ALC221

Flash ROM Yes **CPU Fan Header** Yes **Rear Chassis Fan Header** Yes Front PCI Fan Header Yes Front Control Panel/Speaker Yes

Header

CMOS Battery Holder -Yes

Lithium

Integrated Trusted Platform Trusted Platform Module (TPM) 2.0 (Infineon SLB 9670)

Common Criteria EAL4+ Certified Module

Yes

Yes

Convertible to FIPS 140-2 Certified mode through firmware v7.80

TPM Certified products list:

https://trustedcomputinggroup.org/membership/certification/tpm-certified-products/

Power Supply Headers Power Switch, Power LED &

Hard Drive LED Header

Clear Password Jumper Yes

Serial Port 1 internal header

Parallel Port No

Keyboard/Mouse USB or PS/2

Hood Lock Header Yes **Hood Sensor Header** Yes

Memory Fan 1 Memory Fan Header

AUX IN (audio) No

Power Supply

750W 90% Efficient, Custom PSU 465W 90% Efficient, Custom PSU **Power Supply** (Wide-Ranging, Active PFC) (Wide-Ranging, Active PFC)

Operating Voltage Range 90-269 VAC 90-269 VAC

100-240 VAC 118 VAC 100-240 VAC 118 VAC Rated Voltage Range **Rated Line Frequency** 50-60 Hz 400 Hz 50-60 Hz 400 Hz

Operating Line Frequency 47-66 Hz 393-407 Hz 47-66 Hz 393-407 Hz Range

100-240V @ 10A 100-240V @ 6A **Rated Input Current** 118V @ 10A 118V @ 6A

Heat Dissipation Typical = 1850 btu/hr Typical = 1147 btu/hr (Configuration and software Max = 3084 btu/hr Max = 1912 btu/hr dependent)

80x25 mm variable speed 80x25 mm variable speed **Power Supply Fan**

ENERGY STAR® Certified Yes Yes (Configuration dependent)

90% Efficient 90% Efficient

> The Z4 G4 465W power supply efficiency report The Z4 G4 750W power supply efficiency report

> > can be found at this link: can be found at this link:

https://plugloadsolutions.com/psu_reports/HP% https://plugloadsolutions.com/psu_reports/HP%

20INC_DPS-750AB-20INC_DPS-465AB-

36%20A_750W_ECOS%204938_Report.pdf 3%20A 465W ECOS%204939 Report.pdf

80 PLUS® Compliant

System Technical Specifications

Power Supply 1000W 90% Efficient, Custom PSU (Wide-Ranging, Active PFC)

Operating Voltage Range 90–269 VAC

Rated Voltage Range 100-127 VAC 200-240 VAC 118 VAC

Rated Line Frequency 50–60 Hz 400 Hz

Operating Line Frequency 47–66 Hz 393–407 Hz Range

12A @100-127 VAC

Rated Input Current6.3A @ 200-240 VAC

12A @ 118VAC

Heat Dissipation

(Configuration and software

Typical = 2467 btu/hr

dependent) Max = 4112 btu/hr

Power Supply Fan 80x25 mm variable speed ENERGY STAR® Certified

(Configuration dependent)

90% Efficient

80 PLUS® Compliant The Z4 G4 1000W power supply efficiency report can be found at this link:

https://plugloadsolutions.com/psu_reports/HP_D15-1K0P1A_1000W_ECOS%204838_Report.pdf

FEMP Standby Power
Compliant @115V Yes Yes Yes

<1W in S5 – Power Off)
EuP Compliant @ 230V

(<0.5 W in S5 – Power Off)

Yes

Yes

CECP Compliant @ 220V(<4W in S3 – Suspend to RAM)

Yes; Configuration dependent

Yes; Configuration dependent

Power Consumption in sleep

mode

(as defined by ENERGY TBD TBD

STAR®) – Suspend to RAM

(S3) (Instantly Available PC)

Built-in Self Test LED Yes Yes

Surge Tolerant Full Ranging

Power Supply Yes Yes

(withstands power surges up to 2000V)

NOTE: 1000 W internal power supply, up to 90% efficiency, active PFC available the first half of 2018



System Technical Specifications

System Configuration

Example Z4 G4	Processor	1x Intel Xeon	W-2102 4C 2.9	GHz					
Workstation	Memory	1x 8GB DDR4	x 8GB DDR4-2666 (Registered DIMM)						
Configuration #1	Graphics	1x NVIDIA Qua	adro P400						
ENERGY STAR®	Disks / Optical	1x 500GB SAT	x 500GB SATA 7200 ; 1x Slim DVD-ROM SATA						
Certified	Power Supply	465W 90% custom PSU							
		115	115 VAC 230 VAC 100 VAC						
Energy Consumption		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled		
	Windows Idle (S0)	42	.323	41.	338	42.585			
	Windows Busy Typ(S0)	Т	TBD TBD				TBD		
	Windows Busy Max (S0)	90	90.231 92.323		90.786				
	Sleep (S3)	3.449	3.440	3.566	3.558	3.530	3.410		
	Off (S5)	1.041	1.014	1.242	1.231	1.310	1.180		
	Zero Power Mode (ErP)	0.	187	0.	43	0.1	0.174		
		115	115 VAC		VAC	100	VAC		
Heat Dissipation		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled		
(Btu/hr)	Windows Idle (S0)	144	1.406	141.045		145.301			
	Windows Busy Typ(S0)	T	BD	TBD		TBD			
	Windows Busy Max (S0)	307	7.868	315	.006	309	.761		
	Sleep (S3)	11.767 11.737 12.167 12.140					11.634		
	Off (S5)	3.551	3.459	4.237	4.200	4.469	4.026		
	Zero Power Mode (ErP)	0.	638	1.4	167	0.5	94		

Example Z4 G4	Processor	1x Intel Xeon W-2123 4C 3.6GHz								
Workstation	Memory	2x 8GB DDR4-2666 (Registered DIMM)								
Configuration #2	Graphics	1x NVIDIA Qua	1x NVIDIA QuadroP1000							
ENERGY STAR®	Disks / Optical	1x 500GB SAT	TA 7200 ; 1x Slii	m DVD-ROM S	ATA					
Certified	Power Supply	750W 90% custom PSU								
	Other	N/A								
Energy Consumption		115 VAC 230 VAC 100 VAC					VAC			
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled			
	Windows Idle (S0)	39.947		39.569		40.956				
	Windows Busy Typ(S0)	TBD TBD		TBD		TI	3D			
	Windows Busy Max (S0)	149.543		150.789		147.845				
	Sleep (S3)	3.615	3.566	3.801	3.798	3.634	3.621			
	Off (S5)	1.079	1.016	1.440	1.238	1.320	1.170			
	Zero Power Mode (ErP)	0.	204	0.430		0.191				
						I				
		11:	5 VAC	230	VAC	100	VAC			
Heat Dissipation		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled			



System Technical Specifications

(Btu/hr)	Windows Idle (S0)	136.299		135.009		139.741		
	Windows Busy Typ(S0)	TBD		TBD		TBD		
	Windows Busy Max (S0)	510.241		514.492		504.447		
	Sleep (S3)	12.338	12.167	12.969	12.959	12.399	12.355	
	Off (S5)	3.681	3.466	4.913	4.224	4.504	3.992	
	Zero Power Mode (ErP)		0.696		1.467		0.651	

Example Z4 G4	Processor	1x Intel Xeon W-2133 6C 3.6GHz						
Workstation	Memory	4x 8GB DDR4-2666 (Registered DIMM)						
Configuration #3	Graphics	1x NVIDIA QuadroP2000						
	Disks/Optical	2x 1TB SATA7	'200 ; 1x Slim S	uperMulti DVI	ORW SATA			
	Power Supply	750W 90% cu	stom PSU					
	Other	N/A						
Energy Consumption		115	VAC	230	VAC	100	VAC	
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows Idle (S0)	48.759		46.321		46.578		
	Windows Busy Typ(S0)	TBD		199.56		206.055		
	Windows Busy Max (S0)	209.60		208.66		198.82		
	Sleep (S3)	4.360	4.351	4.538	4.508	4.299	4.277	
	Off (S5)	1.039	1.017	1.42	1.219	1.015	0.997	
	Zero Power Mode (ErP)	0.203		0.399		0.191		
		115	5 VAC	230 VAC		100 VAC		
Heat Dissipation		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled	
(Btu/hr)	Windows Idle (S0)	166	5.366	258.047		158.924		
	Windows Busy Typ(S0)	Т	BD	TBD		TI	3D	
	Windows Busy Max (S0)	715	5.155	711.947		678.373		
	Sleep (S3)	14.876	14.845	15.483	15.381	14.668	14.593	
	Off (S5)	3.544	3.470	4.845	4.179	3.463	3.402	
	Zero Power Mode (ErP)	0.	692	1.3	361	0.651		

Example Z4 G4	Processor	1x Intel Xeon W-2155 10C 3.3GHz							
Workstation	Memory	8x 32GB DDR4-2666 (Registered DIMM)							
Configuration #4	Graphics	1x NVIDIA Qua	1x NVIDIA QuadroP6000						
	Disks / Optical	4x 2TB SATA 7200 ; 0x ODD							
	Power Supply	750W 90% custom PSU							
	Other	N/A							
Energy Consumption		115	VAC	230 VAC		100 VAC			
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled		
	Windows Idle (S0)	65.9	959	69.321		68.635			
	Windows Busy Typ(S0)	ТВ	BD	TBD		TBD			
	Windows Busy Max (S0)	463	.23	456.95		503.125			



System Technical Specifications

	Sleep (S3)	6.336	6.102	6.971	6.189	6.266	6.264	
	Off (S5)	1.047	1.036	1.254	1.222	1.014	0.995	
	Zero Power Mode (ErP)	0.203		0.399		0.191		
		445	VAC	220	MAG			
		115 VAC		230	230 VAC		100 VAC	
Heat Dissipation		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled	
(Btu/hr)	Windows Idle (S0)	225.052		236.523		234.183		
	Windows Busy Typ(S0)	TBD		TBD		TBD		
	Windows Busy Max (S0)	1580.541		1559.113		1716.663		
	Sleep (S3)	21.618	20.821	23.785	21.117	21.379	21.372	
	Off (S5)	3.572	3.534	4.278	4.169	3.459	3.394	
	Zero Power Mode (ErP)	0.6	92	1.3	61	0.6	52	

Example Z4 G4	Processor	1x Intel Core i	7-7800X 3.50	Hz 6C				
Workstation	Memory	2x 8GB DDR4-	2666 (non-E0	CC DIMM)				
Configuration #5	Graphics	1x NVIDIA Quadro P1000						
	Disks / Optical	1x 1TB SATA 7	'200 : 1x Slim	DVD-ROM SA	ΓΑ			
	Power Supply	1000W 90% c	ustom PSU					
	Other	N/A						
Energy Consumption		115	VAC	230	VAC	100	VAC	
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows Idle (S0)	46.9	909	47.	175	46.9	909	
	Windows Busy Typ(S0)	TBD		TBD		TBD		
	Windows Busy Max (S0)	201.83		199.97		203.41		
	Sleep (S3)	3.041	2.971	3.165	3.041	2.971	3.165	
	Off (S5)	0.978	0.898	1.159	0.978	0.898	1.159	
	Zero Power Mode (ErP)	0.1	99	0.379		0.187		
		115	VAC	230 VAC		100 VAC		
Heat Dissipation		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled	
(Btu/hr)	Windows Idle (S0)	160.	053	160.961		160.053		
	Windows Busy Typ(S0)	ТВ	D	TBD		TE	BD	
	Windows Busy Max (S0)	688.	644	682	.297	694.	.035	
	Sleep (S3)	10.376	10.137	10.799	10.376	10.137	10.799	
	Off (S5)	3.337	3.064	3.954	3.337	3.064	3.954	
	Zero Power Mode (ErP)	0.6	78	1.2	193	0.638		

Example Z4 G4	Processor	1x Intel Core i7-7920X 2.9GHz 12C
Workstation	Memory	4x 16GB DDR4-2666 (non-ECC DIMM)
Configuration #6	Graphics	1x NVIDIA Quadro P4000
	Disks / Optical	2x 2TB SATA 7200 : 1x Slim DVD-ROM SATA
	Power Supply	1000W 90% custom PSU



System Technical Specifications

	Other	N/A					
Energy Consumption		115	VAC	230	VAC	100	VAC
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	53.3	392	51.	332	53.	367
	Windows Busy Typ(S0)	ТВ	BD	TE	3D	TBD	
	Windows Busy Max (S0)	318	.58	307.82		319.71	
	Sleep (S3)	3.558	3.486	3.694	3.558	3.486	3.694
	Off (S5)	0.972	0.895	1.160	0.972	0.895	1.160
	Zero Power Mode (ErP)	0.201		0.391		0.186	
		115	VAC	230	VAC	100	VAC
Heat Dissipation		LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Disabled	LAN Enabled
(Btu/hr)	Windows Idle (S0)	182.	174	175.144		182.088	
	Windows Busy Typ(S0)	TB	BD	TBD		TBD	
	Windows Busy Max (S0)	1086	.994	1050.281		1090.851	
	Sleep (S3)	12.139	11.894	12.604	12.139	11.894	12.604
	Off (S5)	3.316	3.054	3.957	3.316	3.054	3.957
	Zero Power Mode (ErP)	0.6	85	1.3	34	0.634	

NOTE: Power consumption measurements do not take advantage of the Intel Turbo Boost Technology. As a result, power consumption measurements may be higher.

DECLARED NOISE EMISSIONS

Declared Noise Emissions (Entry-level and High-end configurations)					
System Configuration	Processor Info	Intel® Xeon® W-2125 4.0 2666 4C CPU			
(Entry level)	Memory Info	32GB (4x8GB) DDR4-2666 ECC Reg RAM			
	Graphics Info	1-NVIDIA® Quadro® P400 2GB			
	Disks/Optical	1-500GB SATA 7200RPM 3.5" HDD / 1-HP 9.5mm Slim Blu Ray Disc Writer			
	Power Supply	465 W			

Declared Noise Emissions (in accordance with ISO		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)
7779 and ISO 9296)	Idle	3.2	13
	Hard drive Operating (random reads)	3.4	15

System Configuration	Processor Info	Intel® Xeon® W-2155 3.3 2666 10C
(High end)	Memory Info	128GB (8x16GB) DDR4-2666 ECC Reg RAM
	Graphics Info	1-NVIDIA® Quadro® P6000 24GB
	Disks/Optical	2-4TB SATA 7200RPM Ent 3.5" / 1-HP 9.5mm Slim Blu Ray Disc Writer
	Power Supply	750 W



System Technical Specifications

Declared Noise Emissio
(in accordance with ISO
7779 and ISO 9296)

	Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)		
Idle	3.5	22		
Hard drive Operating (random reads)	3.7	23		

System	Configuration
(Entry I	evel 2)

Processor Info	Intel® Core i9-7900X 3.3 2666 10C	
Memory Info	32GB (4x8GB) DDR4-2666 nECC RAM	
Graphics Info	1-NVIDIA® Quadro® P400 2GB	
Disks/Optical	1-500GB SATA 7200RPM Ent 3.5" / 1-HP 9.5mm Slim Blu Ray Disc Writer	
Power Supply	1000 W	

Declared Noise Emissions
(in accordance with ISO
7779 and ISO 9296)

	Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)
Idle	3.4	16
Hard drive Operating (random reads)	3.5	17

System	Config	uration
(Hiah er	nd 2)	

Processor Info	Intel®Core i9-7980XE 2.6 2666 18C	
Memory Info	128GB (8x16GB) DDR4-2666 nECC RAM	
Graphics Info	1-NVIDIA® Quadro® P6000 24GB	
Disks/Optical	2-4TB SATA 7200RPM Ent 3.5" / 1-HP 9.5mm Slim Blu Ray Disc Writer	
Power Supply	1000 W	

Declared Noise Emission
(in accordance with ISO
7779 and ISO 9296)

	Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)
Idle	3.5	20
Hard drive Operating (random reads)	3.7	21

NOTE: Higher noise levels may be experienced with non-HP approved graphic card(s). Some consumer graphics cards have side blowing fans that may heat up thermal sensor(s) on the mother board causing fans to ramp.

ENVIRONMENTAL DATA

Environmental Requirements

Temperature Non-operating: -40° to 60° C (-40° to 140° F)

Operating: 5° to 35° C (40° to 95° F)

Above 1524 m (5,000 feet) altitude, the maximum operating temperature is reduced by 1° C (1.8° F) for every 305 m (1,000 feet) increase in elevation

Maximum rate of change: 10 °C/hr

No direct sustained sunlight

Humidity Operating: 10% to 85% RH, non-condensing, 35° C maximum wet bulb



System Technical Specifications

Non-operating: 10% to 90% RH, non-condensing, 35° C maximum wet bulb

Maximum Altitude Operating (with Rotational Hard Drives): 3,048 m (10,000 feet)

Operating (with only Solid-State Drives): 5,000 m (16,404 feet)

Non-operating: 12,192 m (40,000 feet)

Maximum operating temperature is reduced as altitude increases. See

Temperature for details.

Shock (non-repetitive) Operating: 1/2-sine: 40g, 2-3ms (~62 cm/sec)

Non-operating: 1/2-sine: 160 cm/s, 2-3ms (~105g)

Non-operating square: 422 cm/s, 20g

Vibration Operating random: 0.5g (rms), 5-300 Hz, up to 0.0025g²/Hz

Non-operating random: 2.0g (rms), 5-500 Hz, up to 0.0150 g²/Hz

Physical Security and Serviceability

Access Panel Tool-less

Includes system board and memory information.

Hard Drives Tool-less **Expansion Cards** Tool-less **Processor Socket** Tool-less

Blue User Touch Points Yes, on primary serviceable components.

Color-coordinated Cables Yes

and Connectors

Memory Tool-less **System Board** Screw-In **Dual Color Power/Failure** Yes

LED

HDD Activity LED

Note: HDD Activity LED is not dual-color

Configuration Record SW Yes

Over-Temp Warning on Yes, at POST screen on reboot

Screen

Restore CD/DVD Set Restores the computer to its original factory shipping image; can be obtained via HP Support.

Dual Function Front

Power Switch

Padlock Support Yes (optional): Locks side cover and secures chassis from theft

7.0 mm (0.2756 in) diameter padlock loop at rear of system

Cable Lock Support Yes, Kensington Cable Lock (optional): Locks side cover and secures chassis from theft

Yes, causes a fail-safe power off when held for 4 seconds

3 mm x 7 mm slot at rear of system

Universal Chassis Clamp

Lock Support

Yes (optional): Locks side cover and locks cables to chassis. Secures chassis from theft and allows

multiple units to be chained together when used with optional cable Threaded feature at rear of system

Solenoid Lock and Hood Yes (optional)

Sensor The Solenoid Hood Lock eliminates the need for a physical key by making the chassis lockable through

software and a password. You can also lock and unlock the chassis remotely over the network. The

Sensor Kit detects when the access panel has been removed



System Technical Specifications

Serial, Parallel, USB, Audio, Network, **Enable/Disable Port**

Yes, enables or disables serial, USB, audio, and network ports

Control

Removable Media Write/Boot Control Yes, prevents ability to boot from removable media on supported devices (and can disable writes to

media)

Power-On Password

Setup Password

Yes, prevents an unauthorized person from booting up the workstation

Yes, prevents an unauthorized person from changing the workstation configuration

3.3V Aux Power LED on

System PCA

Yes

NIC LEDs (integrated)

(Green & Amber)

Yes

CPUs and Heatsinks

A T-15 Torx or flat blade screwdriver is needed to remove the CPU heatsink before the CPU can be

removed. CPU removal is tool-less

Power Supply Diagnostic Yes

Front Power Button Yes, ACPI multi-function

Rear Power Button

Front Power LED Yes, white (normal), red (fault)

Front Hard Drive Activity Yes, white

Front ODD Activity LED **Internal Speaker**

Flash Recovery

System/Emergency ROM Recovers corrupted system BIOS.

Cooling Solutions Air cooled forced convection heatsinks **Power Supply Fans** 80 mm x 80 mm x 25 mm (non-serviceable)

Yes, on device

CPU Heatsink Fan

Intel® Xeon® W Processor Family

Intel® Core™ X-series Processors

92 mm x 92 mm x 25 mm, 5-wire, PWM

Core i7-X configs: 92 mm x 92 mm x 25 mm, 5wire, PWM

Core i9-X 165W CPU configs: 92 mm x 92 mm x 25 mm, 6-wire, PWM (includes 6-to-5pin cable

adapter)

NOTE: Core i9X 140W use the same Heatsink as

Core i7X and Xeon

Chassis Fan

(Optional) 92 mm x 92mm x 25 mm, 4-wire, PWM

Rear:

120 mm x 120mm x 25 mm, 4-wire, PWM

Memory Heatsink Fan HP PC Hardware Diagnostics UEFI

Dual 60 mm x 60 mm x 25 mm, 6-wire, PWM, Blindmate (optional based on configuration)

HP PC Hardware Diagnostics (UEFI) enables hardware level testing outside the operating system on many components. The diagnostics can be invoked by pressing ESC then F2 upon the PC reboot, and is

available as a download from HP Support.

Access Panel Key Lock ACPI-Ready Hardware

Yes, side panel barrel keylock (optional from the factory only) Advanced Configuration and Power Management Interface (ACPI).

Allows the system to wake from a low-power mode.



System Technical Specifications

Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system

Trusted Platform Module Infineon TPM 2.0 Certified

Chip

Integrated Chassis

Handles

Yes, Front handle and dedicated rear recess

Power Supply

Requires T15 Torx or flat blade screwdriver

PCIe Card Retention

Yes, rear (all), middle (all), front (full-length cards with extender, using HP Z4 G4 Fan and Front Card

Guide Kit)

Flash ROM Yes Diagnostic Power Switch Yes

LED on board

Yes

Clear Password Jumper Clear CMOS Button Yes CMOS Battery Holder Yes **DIMM Connectors** Yes

BIOS

BIOS 32-bit Services

Standard BIOS 32-bit Service Directory Proposal v0.4

PCI 3.0 Support

Full BIOS support for PCI Express through industry standard interfaces.

ATAPI

ATAPI Removable Media Device BIOS Specification Version 1.0.

BBS

BIOS Boot Specification v1.01.

WMI Support

WMI is Microsoft's implementation of Web-Based Enterprise Management (WBEM) for Windows. WMI is fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM)

and WBEM specifications.

BIOS Boot Spec 1.01+

Provides more control over how and from what devices the workstation will boot.

BIOS Power On

Users can define a specific date and time for the system to power on.

ROM Based Computer

Review and customize system configuration settings controlled by the BIOS.

Setup Utility (F10) System/Emergency ROM

Recovers system BIOS in corrupted Flash ROM.

Flash Recovery with

Video

Replicated Setup

Saves BIOS settings to USB flash device in human readable file (HpSetup.txt). BiosConfigUtility.exe

utility can then replicate these settings on machines being deployed without entering Computer

Configuration Utility (F10 Setup).

SMBIOS Boot Control System Management BIOS 2.8, for system management information. Disables the ability to boot from removable media on supported devices.

Memory Change Alert **Thermal Alert**

Alerts management console if memory is removed or changed. Monitors the temperature state within the chassis. Three modes:

• NORMAL - normal temperature ranges.

ALERTED - excessive temperatures are detected. Raises a flag so action can be taken to avoid

shutdown or provide for a smoother system shutdown.

• SHUTDOWN - excessive temperatures are encountered. Automatically shuts down the computer

without warning before hardware component damage occurs.

Remote ROM Flash

Provides secure, fail-safe ROM image management from a central network console. Allows the system to enter and resume from low power modes (sleep states).

ACPI (Advanced Configuration and Power Management Interface)

Enables an operating system to control system power consumption based on the dynamic workload. Makes it possible to place individual cards and peripherals in a low-power or powered-off state without

affecting other elements of the system.



System Technical Specifications

Supports ACPI 5.0 for full compatibility with 64-bit operating systems.

Ownership Tag A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen.

Shutdown

Remote Wakeup/Remote System administrators can power on, restart, and power off a client computer from a remote location with Intel Xeon W Processors. For systems with Intel Core X-Series Processors, Wake on LAN is supported, however to remotely restart or shutdown a system, a remote desktop application must be used to manually Restart or Shutdown.

Instantly Available PC (Suspend to RAM - ACPI Allows for very low power consumption with quick resume time.

sleep state S3) **Remote System**

Allows a new or existing system to boot over the network and download software, including the operating system.

Installation via F12 (PXE 2.1) (Remote Boot from Server)

ROM revision levels Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup). Version is available through an industry standard interface (SMBIOS and WMI) so that management SW

applications can use and report this information.

System board revision

Allows management SW to read revision level of the system board. Revision level is digitally encoded into the HW and cannot be modified. Assesses system health at boot time with selectable levels of testing.

Start-up Diagnostics (Power-on Self-Test)

level

Auto Setup when new hardware installed **Keyboard-less Operation** The system can be booted without a keyboard.

System automatically detects addition of new hardware.

Localized ROM Setup

Common BIOS image supports System Configuration Utility (F10 Setup) menus in 14 languages with

local keyboard mappings.

Asset Tag The user or MIS to set a unique tag string in non-volatile memory.

Per-slot Control Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually. **Adaptive Cooling** Control parameters are set according to detected hardware configuration for optimal acoustics. (Pre-video) critical errors are reported via beeps and blinks on the power LED.

Pre-boot Diagnostics Industry Standard Specification Support

Industry Standard Revision Supported by the BIOS

UEFI Specification

Revision

PCI Express

2.5

ACPI Advanced Configuration and Power Management Interface, Version 5.0 ATA (IDE) AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b **CD Boot** "El Torito" Bootable CD-ROM Format Specification Version 1.0

EDD - Enhanced Disk Drive Specification Version 1.1

- BIOS Enhanced Disk Drive Specification Version 3.0

EHCI Enhanced Host Controller Interface for Universal Serial Bus. Revision 1.0

PCI Express Base Specification, Revision 3.0

PCI PCI Local Bus Specification, Revision 2.3

PCI Power Management Specification, Revision 1.1 PCI Firmware Specification, Revision 3.0, Draft .7 PCI Express Base Specification, Revision 2.0

PMM POST Memory Manager Specification, Version 1.01

SATA Serial ATA Specification, Revision 1.0a

> Serial ATA 3 Gb/s: Serial ATA Specification, Revision 2.5 Serial ATA 6 Gb/s: Serial ATA Specification, Revision 3.0

SPD PC SDRAM Serial Presence Detect (SPD) Specification, Revision 1.2B

TPM Trusted Platform Module (TPM) 2.0 (Infineon SLB 9670)



System Technical Specifications

Common Criteria EAL4+ Certified

Convertible to FIPS 140-2 Certified mode through firmware v7.80

TCG TPM Certified products list:

http://www.trustedcomputinggroup.org/certification/tpm-certified-products/

UHCI Universal Host Controller Interface Design Guide, Revision 1.1

USB Universal Serial Bus Revision 1.1 Specification

> Universal Serial Bus Revision 2.0 Specification Universal Serial Bus Revision 3.1 G1 Specification Universal Serial Bus Revision 3.1 G2 Specification

SMBIOS System Management BIOS Reference Specification, Version 2.8

External BIOS simulator found at: http://h20464.www2.hp.com/index.html

Social and Environmental Responsibility

Eco-Label Certifications & This product has received or is in the process of being certified to the following approvals and may be **Declarations** labeled with one or more of these marks:

- ENERGY STAR® (energy-saving features available on selected configurations-Windows only)
- US Federal Energy Management Program (FEMP)
- China Energy Conservation Program
- The ECO declaration (TED)

The Z4 G4 is registered EPEAT® Gold in the US and Canada. EPEAT® registration varies by country. See http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options

Batteries The battery in this product complies with EU Directive 2006/66/EC

Battery mass: 3a

Battery type: Lithium Metal

The battery in this product does not contain:

- Mercury greater than 5ppm by weight
- Cadmium greater than 10ppm by weight
- Lead greater than 40ppm by weight

Restricted Material Usage This product meets the material restrictions specified in HP's General Specification for the Environment.

HP Inc. is committed to compliance with all applicable environmental laws and regulations, including the European Union Restriction of Hazardous Substances (RoHS) Directive. HP's goal is to exceed compliance obligations by meeting the requirements of the RoHS Directive on a worldwide basis

Low Halogen Statement

This product is low-halogen except for power cords, external cables and peripherals. Service parts obtained after purchase may not be low-halogen.

and Recycling

End-of-Life Management HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. This product is greater than 90% recyclable by weight when properly disposed of at end of life.



System Technical Specifications

HP Inc. Corporate Environmental Information **Additional Information** For more information about HP's commitment to the environment:

Sustainability Report

Eco-label certifications ISO 14001 certificates

- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. Product Disassembly Instructions
- Plastic parts weighing over 25 grams used in the product are marked per ISO 11469 and IS01043.

Packaging

HP Workstation product packaging meets the HP's General Specification for the Environment

- Does not contain restricted substances listed in HP Standard 011-1 General Specification for the Environment
- Does not contain ozone-depleting substances (ODS)
- Does not contain heavy metals (lead, mercury, cadmium or hexavalent chromium) in excess of 100 ppm sum total for all heavy metals listed
- Maximizes the use of post-consumer recycled content materials in packaging materials
- All packaging material is recyclable
- All packaging material is designed for ease of disassembly
- Reduced size and weight of packages to improve transportation fuel efficiency
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards formatting

Packaging Materials Internal **External**

Cushions and plastic bags made of low density polyethylene (LDPE). Outer carton, accessories carton, and insert made of corrugated paper board.

Manageability

Industry Standard Specifications

Technology (AMT)

Intel® Xeon® W Processor Family

This product meets the following industry standard specifications for manageability functionality:

DASH 1.1 (via Intel® LAN on motherboard) Intel Active Management Intel® Active Management Technology (AMT) 11.10

> An advanced set of remote management features and functionality providing IT administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state. AMT 11.10 includes the following advanced management functions:

- Power Management (on, off, reset, graceful shutdown, sleep and hibernate)
 - **Support in Max Power Savings** (Shutdown and Hibernate Modes)
- Hardware Inventory (includes BIOS and firmware revisions)
- Hardware Alerting
- Agent Presence
- **System Defense Filters**
- Serial Over LAN (SOL)
- **USB Redirect (Media Redirection)**

Intel® Core™ X-series Processors None apply



System Technical Specifications

- ME Wake-on-LAN (WOL), even with Maximum Power Savings Enabled
- DASH 1.1 compliance
- IPv6 Support
- Fast Call for Help a client inside or outside the firewall may initiate a call for help via BIOS screen, periodic connections, or alert triggered connection
- Remote Scheduled Maintenance preschedule when the system connects to the IT or service provider console for maintenance.
- Remote Alerts automatically alert IT or service provider if issues arise
- Access Monitor Provides oversight into Intel® AMT actions to support security requirements
- PC Alarm Clock
- Microsoft NAP Support
- Host Base set-up and configuration
- Management Engine (ME) firmware roll back
- Local Time Sync to UTC
- Remote Memory Dump Command Creates memory dump for debug

Intel® vPro™ Technology

The HP Z4 G4 Workstation supports Intel® vPro™ technology when configured as outlined below:

Not supported

- Intel® Xeon® processor W-2100 product family featuring Intel® vPro™ Technology
- Intel[®] C422 chipset
- Intel® I219LM GbE LAN

Remote Manageability Software Solutions

The HP Z4 G4 Workstation is supported on the following optional remote manageability software consoles:

- Microsoft System Center Configuration Manager

LANDesk Management Suite (HP

recommended solution)

For questions or support for manageability needs, please visit

http://www.hp.com/go/easydeploy

System Software Manager Service, Support, and Warranty For easydeploy questions or support for SSM, please visit: http://www.hp.com/go/ssm

On-site Warranty and Service (Note 1): Three-years, limited warranty and service offering delivers on-site, next business-day (Note 2) service for parts and labor and includes free telephone support (Note 3) 8am - 5pm. Global coverage (Note 2) ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering. 24/7 operation will not void the HP warranty.

Microsoft System Center Configuration

Manager



System Technical Specifications

NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply.

NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

NOTE 3: Technical telephone support applies only to HP-configured, HP and HP-qualified, third-party hardware and software. Toll-free calling and 24x7 support service may not be available in some countries.

HP Care Pack Services extend service contracts beyond the standard warranties. Service starts from date of hardware purchase. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/lookuptool. Service levels and response times for HP Care Packs may vary depending on your geographic location.

- Program to proactively communicate Product Change Notifications (PCNs) and Customer Advisories by email to customers, based on a user-defined profile.
- PCNs provide advance notification of hardware and software changes to be implemented in the factory providing time to plan for transition.
- Customer Advisories provide concise, effective problem resolution, greatly reducing the need to call technical support.

Product Change Notification

Stable & Consistent Offerings

As part of its commitment to hardware, software, and solution innovation, HP is proud to introduce this breakthrough platform configuration stability to HP Workstation customers. HP Stable & Consistent Offerings are built on the foundation of a carefully chosen set of hardware designed and tested to work with all HP Z Workstation platforms through their end of life. These components and their corresponding HP Workstation platform compatibility are outlined in this section.

HP Stable & Consistent Offerings are available worldwide to all HP Workstation customers-no special programs, no additional cost-no kidding. Simply select your hardware components when you customize your HP Workstation and be assured that you'll be able to buy that same configuration throughout the lifecycle of the product.

		ery are or and products	
Processors	Product #	Offering	
	TBD	Intel® Xeon® W-2125 4.0 2666 4C CPU	
	TBD	Intel® Xeon® W-2123 3.6 2666 4C CPU	
	TBD	Intel® Xeon® W-2102 2.9 2400 4C CPU	
Hard Drives	Product #	Offering	
	LQ037AA	1TB SATA 7200 RPM	
Graphics	Product #	Offering	
	2TF08AA	AMD Radeon™ Pro WX 3100 4GB Graphics	
Memory	Product #	Offering	
	TBD	TBD	
Optical and Removable	Product #	Offering	
Storage	TBD	TBD	
	TBD	TBD	



Technical Specifications - Processors

Intel® Xeon® W-2100 Series CPU

Intel® Xeon® W-2195 2.3 2666 18C CPU

Intel® Xeon® W-2175 2.5 2666 14C CPU

Intel® Xeon® W-2155 3.3 2666 10C CPU

Intel® Xeon® W-2145 3.7 2666 8C CPU

Intel® Xeon® W-2135 3.7 2666 6C CPU

Intel® Xeon® W-2133 3.6 2666 6C CPU

Intel® Xeon® W-2125 4.0 2666 4C CPU

Intel® Xeon® W-2123 3.6 2666 4C CPU

Intel® Xeon® W-2104 3.2 2400 4C CPU

Intel® Xeon® W-2102 2.9 2400 4C CPU

Intel® Core™ X-Series CPU

Intel® Core™ i9-7980XE 2.6 2666 18C CPU

Intel® Core™ i9-7960X 2.8 2666 16C CPU

Intel® Core™ i9-7940X 3.1 2666 14C CPU

Intel® Core™ i9-7920X 2.9 2666 12C CPU

Intel® Core™ i9-7900X 3.3 2666 10C CPU

Intel® Core™ i7-7820X 3.6 2666 8C CPU

Intel® Core™ i7-7800X 3.5 2400 6C CPU



Technical Specifications - Hard Drives

STORAGE/HARD DRIVES

Workstations

Capacity300GBHeight5.9 in; 15 cm

Width Media Diameter 3.5 in; 8.9 cm

Interface 12Gb/s SAS

Synchronous Transfer Up to 1200 MB/s (SAS single port)

Rate (Maximum)

Buffer 128MB

Seek Time (typical reads, Average 2.0ms

includes controller overhead, including

settling)

Rotational Speed 15K rpm

Operating Temperature 41° to 131° F (5° to 55° C)



Technical Specifications - Hard Drives

SATA (Serial ATA) Hard Drives for HP Workstations 500GB SATA 7200 rpm 6Gb/s 3.5" HDD Capacity 500GB
Height 1 in; 2.54 cm
Width Media Diamet

Media Diameter3.5 in; 8.9 cmPhysical Size4 in; 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer Up to 600MB/s

Rate (Maximum)

Buffer 16MB

Seek Time (typical reads,
includes controller
overhead, including
settling)Single Track
Average2 ms11 ms
Full Stroke21 ms

Rotational Speed 7,200 rpm **Logical Blocks** 976,773,168

Operating Temperature 41° to 131° F (5° to 55° C)

1TB SATA 7200 rpm 6Gb/s 3.5" HDD Capacity 1TB

Height 1 in; 2.54 cm

Width Media Diameter 3.5 in; 8.9 cm
Physical Size 4 in; 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Up to 600 MB/s

Buffer 64MB Cache Adaptive

Seek Time (typical reads,
includes controller
overhead, including
and includingSingle Track
Average2 msFull Stroke21 ms

settling)

Rotational Speed 7,200 rpm

Operating Temperature 41° to 131° F (5° to 55° C)

2.0TB SATA 7200 rpm 6Gb/s 3.5" HDD Capacity2.0TBHeight1 in; 2.54 cm

Width Media Diameter 3.5 in; 8.9 cm Physical Size 4 in; 10.17 cm

Interface Serial ATA (6.0 Gb/s), NCQ Enabled

Synchronous Transfer

Rate (Maximum)

Up to 600 MB/s

Buffer 64MB

Seek Time (typical reads,
includes controller
overhead, includingSingle Track
Average1.0 ms11 ms
Full Stroke18 ms

settling)

Rotational Speed 7,200 rpm Logical Blocks 3,907,029,168

Technical Specifications - Hard Drives

Operating Temperature 41° to 131° F (5° to 55° C)

1TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class) Capacity 1TB
Protocol SATA
Form Factor 3.5"
Controller AHCI
Reliability (MTBF) 2.0M ho

Reliability (MTBF) 2.0M hours
Rated Power On Hours 8760/yr
Annualized Failure Rate <0.62%

(based on Rated POH)
Rated for 24/7/365

operation

YES

Physical Size (Height)1 in; 2.54 cmPhysical Size (Width)4 in; 10.17 cmMedia Diameter3.5 in; 8.9 cm

Interface Serial ATA (6Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Up to 600MB/s

Buffer 128MB

Seek Time (typical reads,
includes controller
overhead, including
settling)Single Track
Average0.32msAverage
Full Stroke7.45ms14.2ms

Operating Temperature 41° to 140° F (5° to 60° C)

Performance Sequential Read up to 226MB/s

Sequential Write up to 226MB/s

Enterprise Class Features High Reliability

Technical Specifications - Hard Drives

4TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)

Capacity 4TB

Height 0.275 in; 0.7 cm

Width **Media Diameter** 2.5 in; 6.36 cm **Physical Size** 2.75 in; 6.99 cm

Interface Serial ATA (6Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Up to 600MB/s

Buffer 128MB

Seek Time (typical reads, **Single Track** 0.7ms includes controller **Average** 8.5ms overhead, including **Full Stroke** 15.7ms

settling)

Rotational Speed 7,200 rpm

32° to 140° F (0° to 60° C) **Operating Temperature**

500GB SATA 7.2K SED SFF HDD

Capacity 500GB

Height 0.275 in: 0.7 cm

Width **Media Diameter** 2.5 in; 6.36 cm **Physical Size** 2.75 in; 6.99 cm

Serial ATA (6Gb/s)

Full Stroke

1ms

4.2ms

25ms (typical)

Interface **Synchronous Transfer** Up to 600MB/s

Rate (Maximum)

Buffer **32MB**

Seek Time (typical reads, Single Track includes controller **Average** overhead, including

settling)

Rotational Speed 7,200 rpm

Operating Temperature 32° to 140° F (0° to 60° C)

Technical Specifications - Hard Drives

SATA SSDs for HP
Workstations

HP 256GB SATA 6Gb/s SSD

Capacity 256GB **Protocol** SATA **Form Factor** 2.5" Controller **AHCI NAND Type** 3D TLC

Endurance 192TBW (TB Written)

Reliability (MTTF) 1.5M hours Physical Size (Height) 0.28 in; 0.7 cm Physical Size (Width) 2.5 in; 6.36 cm Interface SATA 6Gb/s **Synchronous Transfer** Up to 600MB/s

Rate (Maximum)

Performance

32° to 158° F (0° to 70° C)

Operating Temperature

Sequential Read 530MB/s (max)

Sequential Write 500MB/s (max) **Random Read** 55K IOPS (max) **Random Write** 83K IOPS (max)

HP 256GB SATA 6Gb/s SED Opal 2 SSD

Capacity 256GB **Protocol** SATA **Form Factor** 2.5" Controller **AHCI NAND Type** 3D TLC

Endurance 192TBW (TB Written)

Reliability (MTTF) 1.5M hours Physical Size (Height) 0.28 in: 0.7 cm Physical Size (Width) 2.5 in; 6.36 cm Interface 6Gb/s SATA

Synchronous Transfer Rate (Maximum)

Up to 550MB/s (Sequential Read)

Operating Temperature

32° to 158° F (0° to 70° C)

Sequential Read 530MB/s **Sequential Write** 500 MB/s **Random Read 55K IOPS Random Write 83K IOPS**

Self-Encrypting Drive

Support

Performance

OPAL 2

HP 512GB SATA 6Gb/s SSD

Capacity 512GB Protocol SATA **Form Factor** 2.5" Controller **AHCI NAND Type** 3D TLC

Endurance 388TBW (TB Written)

Reliability (MTTF) 1.5M hours

Technical Specifications - Hard Drives

Physical Size (Height)0.28 in; 0.7 cmPhysical Size (Width)2.5 in; 6.36 cmInterfaceSATA 6Gb/s

Synchronous Transfer Rate (Maximum)

Up to 550MB/s (Sequential Read)

Operating Temperature

32° to 158° F (0° to 70° C)

Performance

Sequential Read 530 MB/s
Sequential Write 500 MB/s
Random Read 95K IOPS
Random Write 83K IOPS

HP 512GB SATA SED SSD

Capacity512GBProtocolSATAForm Factor2.5"ControllerAHCINAND Type3D TLC

Endurance 388TBW (TB Written)

Reliability (MTTF)1.5M hoursPhysical Size (Height)0.28 in; 0.7 cmPhysical Size (Width)2.5 in; 6.36 cmInterfaceSATA 6Gb/sSynchronous TransferUp to 600MB/s

Synchronous Transfer Rate (Maximum) Operating Temperature

32° to 158° F (0° to 70° C)

Performance Segu

Sequential Read 530 MB/s
Sequential Write 500 MB/s
Random Read 95K IOPS
Random Write 83K IOPS

Self-Encrypting Drive

Support

OPAL 1 and 2

HP 1TB SATA 6Gb/s SSD

Capacity1TBProtocolSATAForm Factor2.5"ControllerAHCINAND Type3D TLC

Endurance 400TBW (TB Written)

Reliability (MTTF)1.5M hoursPhysical Size (Height)0.28 in; 0.7 cmPhysical Size (Width)2.5 in; 6.36 cmInterfaceSATA 6Gb/s

Synchronous Transfer

Rate (Maximum)

Up to 550MB/s (Sequential Read)

Operating Temperature

32° to 158° F (0° to 70° C)

Performance Sequential Read 530 MB/s

Technical Specifications - Hard Drives

Random Read95K IOPSRandom Write83K IOPS	
HP 2TB SATA 6Gb/s SSD Capacity 2TB	
Protocol SATA	
Form Factor 2.5"	
Controller AHCI	
NAND Type 3D TLC	
Endurance 400TBW (TB Written)	
Reliability (MTTF) 1.5M hours	
Physical Size (Height) 0.28 in; 0.7 cm	
Physical Size (Width) 2.5 in; 6.36 cm	
Interface SATA 6Gb/s	
Synchronous Transfer Up to 550MB/s (Sequential Read) Rate (Maximum)	
Operating Temperature 32° to 158° F (0° to 70° C)	
Performance Sequential Read 530 MB/s	5
Sequential Write 500 MB/s	5
Random Read 95K IOPS	;
Random Write 83K IOPS	;
HP Enterprise Class Capacity 240GB	
240GB SATA SSD Protocol SATA	
Form Factor 2.5"	
Controller AHCI	
NAND Type 3D TLC	
Endurance 2,200TBW (TB Written)	
Reliability (MTTF) 2.0M hours	
Physical Size (Height) 0.28 in; 0.7 cm	
Physical Size (Width) 2.5 in; 6.36 cm	
Interface 6Gb/s SATA	
Synchronous Transfer Up to 600MB/s Rate (Maximum)	
Operating Temperature 32° to 158° F (0° to 70° C)	
Performance Sequential Read 540 MB/s	5
Sequential Write 310 MB/s	5
Random Read 93K IOPS	;
Random Write 48K IOPS	;
Enterprise Class Features High Endurance NAND Power Loss Protection End-to-End Data Protection	
HP Enterprise Class Capacity 480GB	
480GB SATA SSD Protocol SATA	
Form Factor 2.5"	

Technical Specifications - Hard Drives

Controller AHCI NAND Type 3D TLC

Endurance 4,400TBW (TB Written)

Reliability (MTTF) 2.0M hours
Physical Size (Height) 0.28 in; 0.7 cm
Physical Size (Width) 2.5 in; 6.36 cm
Interface 6Gb/s SATA
Synchronous Transfer Up to 600MB/s

Synchronous Transformate (Maximum)

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 540 MB/s

Sequential Write 460 MB/s Random Read 93K IOPS Random Write 74K IOPS

Enterprise Class Features High Endurance NAND

Power Loss Protection End-to-End Data Protection

PCIe SSDs for HP Workstations

HP Z Turbo Drive G2 256GB SSD Capacity256GBProtocolPCIeForm FactorM.2ControllerNVMeNAND TypeMLCEndurance150TBReliability (MTBF)1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 2800 MB/s

Sequential Write1100 MB/sRandom Read250K IOPSRandom Write180K IOPS

HP Z Turbo Drive G2 512GB SSD Capacity 512GB
Protocol PCIe
Form Factor M.2
Controller NVMe
NAND Type 3D MLC
Endurance 300TB
Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 2800 MB/s
Sequential Write 1600 MB/s

Technical Specifications - Hard Drives

		Random Read	260K IOPS
		Random Write	260K IOPS
UD 7 Tumb a Duine C2 4TD	Canaditu	170	
HP Z Turbo Drive G2 1TB	Capacity	1TB	
SSD	Protocol	PCIe	
	Form Factor	M.2	
	Controller	NVMe	
	NAND Type	3D MLC	
	Endurance	600TB	
	Reliability (MTTF)	1.5M hours	
	Interface	PCI Express 3.0 x4 el	ectrical x4 physical
	Operating Temperature	32° to 158° F (0° to 7	0° C)
	Performance	Sequential Read	3000 MB/s
		Sequential Write	1700 MB/s
		Random Read	360K IOPS
		Random Write	330K IOPS

Technical Specifications - Hard Drives

HP Z Turbo Drive Quad Pro 2x256GB PCIe SSD **Capacity** 512GB **Protocol** PCIe

Form Factor PCIe Card, Full Height PCIe Slot

ControllerNVMeNAND TypeMLCEndurance150TBReliability (MTBF)1.5M hours

Interface PCIe Gen3 x4 architecture **Operating Temperature** 32° to 158° F (0° to 70° C)

Performance Sequential Read 2800 MB/s

Sequential Write1100 MB/sRandom Read250K IOPSRandom Write180K IOPS

HP Z Turbo Drive Quad Pro 2x512GB PCIe SSD Capacity 1TB Protocol PCIe

Form Factor PCIe Card, Full Height PCIe Slot

ControllerNVMeNAND TypeMLCEndurance292TBReliability (MTBF)1.5M hours

Interface PCIe Gen3 x4 architecture **Operating Temperature** 32° to 158° F (0° to 70° C)

Performance Sequential Read 2800 MB/s
Sequential Write 1600 MB/s
Random Read 250 K IOPS

Random Write 180K IOPS

HP Z Turbo Drive G2 256GB SED SSD Capacity 256GB Protocol PCIe

Form Factor Half-height, half-length

Controller NVMe NAND Type MLC

Endurance 150TBW (TB Written)

Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 2800 MB/s

Sequential Write1100 MB/sRandom Read250K IOPSRandom Write180K IOPS

Technical Specifications - Hard Drives

Self-Encrypting Drive

Support

OPAL 2

HP Z Turbo Drive G2 512GB SED SSD

Capacity 512GB **Protocol PCIe**

Form Factor Half-height, half-length

Controller NVMe **NAND Type** 3D MLC

300TBW (TB Written) **Endurance**

Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature

32° to 158° F (0° to 70° C)

Performance

Sequential Read 2800 MB/s **Sequential Write** 1600 MB/s **Random Read 260K IOPS Random Write 150K IOPS**

Self-Encrypting Drive

Support

OPAL 2

2TB

PCIe

HP Z Turbo Drive Quad Pro Capacity 2x1TB PCIe SSD **Protocol**

> **Form Factor** PCIe Card, Full Height PCIe Slot

Controller NVMe **NAND Type** 3D MLC **Endurance** 600TB

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature

Performance

32° to 158° F (0° to 70° C)

Sequential Read 3000 MB/s **Sequential Write** 1700 MB/s **Random Read 360K IOPS Random Write 330K IOPS**

HP Z Turbo Drive G2 256GB TLC SSD

Capacity 256GB **PCIe Protocol Form Factor** M.2 NVMe Controller **NAND Type** 3D TLC

Endurance 75TBW (TB Written)

Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 2800 MB/s

> **Sequential Write** 320 MB/s (1100 MB/s

> > max/Turbo)

Random Read 250K IOPS

180K IOPS

QuickSpecs

Technical Specifications - Hard Drives

512GB TLC SSD

HP Z Turbo Drive G2	Capacity	512GB	

 Protocol
 PCIe

 Form Factor
 M.2

 Controller
 NVMe

 NAND Type
 3D TLC

Endurance 150TBW (TB Written)

Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Random Write

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 2800 MB/s

Sequential Write 660 MB/s (1600 MB/s

max/Turbo)

Random Read 260K IOPS **Random Write** 260K IOPS

HP Z Turbo Drive G2 1TB TLC SSD

Capacity1TBProtocolPCIeForm FactorM.2ControllerNVMeNAND Type3D TLC

Endurance 300TBW (TB Written)

Reliability (MTBF) 1.5M hours

Interface PCI Express 3.0 x4 electrical x4 physical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3000 MB/s

Sequential Write 1150 MB/s (1700 MB/s

max/Turbo)

Random Read 360K IOPS
Random Write 330K IOPS



Technical Specifications - Hard Drive Controllers

HARD DRIVE CONTROLLERS

MicroSemi 2100-4i4e 8port SAS 12Gb/s RAID Card **PCI Bus** 8 lanes, PCI Express 3.0

RAID LevelsOffers Integrated RAID (0, 1, and 10) **PCI Data Burst Transfer**Half Duplex x8, PCIe, 8000 MB/s

Rate

SAS Bandwidth Half Duplex 1200 MB/s per lane

PCI Card Type 3.3V Add-in Card PCI Voltage 12 V ± 10%

PCI Power 9.8W typical, Airflow min 200 LFM

Bracket Full height and low profile **Certification Level** PCI Express 3.0 compliant

SAS ProcessorMicroSemi Series 8 SAS ControllerInternal ConnectorsOne x4 internal mini-SASHD (SFF-8643)External ConnectorsOne x4 external mini-SASHD (SFF-8644)

Maximum Number of SCSI 256 Non-RAID SAS/SATA devices

Devices

LED Indicators Connector for Drive Activity Light



Technical Specifications - Graphics

GRAPHICS

NVIDIA® Quadro® P400

2GB Graphics

Form Factor Dimensions: 2.713" H x 5.7" L

Single Slot, Low Profile

Cooling: Active Weight: 129 grams

Graphics Controller NVIDIA® Quadro® P400 Graphics Card

GP107-825 GPU

256 NVIDIA® CUDA® cores Max Power: 30 Watts

Bus Type PCI Express 3.0 x16

Memory Size: 2 GB GDDR5, 2000 MHz

Memory Interface: 64-bit Memory Bandwidth: 32 GB/s

Connectors 3mDP Outputs

Maximum Resolution DisplayPort™ 1.4:

- up to 3x 5120 x 2880 x 24 bpp @ 60Hz- supports Multi-Stream Transport (MST)

Image Quality Features 10-bit internal display processing pipeline

10-bit scan-out support

Display Output 3 mDP Connectors

Shading Architecture Full Microsoft DirectX® 12 Shader Model 5.1

Supported Graphics APIs OpenGL® 4.5

DirectX® 12 Vulkan™ 1.0

API support includes:

CUDA C, CUDA C++, DirectCompute, OpenCL™

Available Graphics

Drivers

Microsoft Windows 10 Microsoft Windows 8.1 Microsoft Windows 7

Linux®

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes

NVIDIA® Quadro® P600 1st Form Factor

GFX 2GB Graphics

Dimensions: 2.713" H x 5.7" L Single Slot, Low Profile

Cooling: Active
Weight: 129 grams

Graphics Controller NVIDIA® Quadro® P600 Graphics Card

GP107-850 GPU 384 NVIDIA® CUDA® cores

Max Power: 40 Watts



Technical Specifications - Graphics

Bus Type PCI Express 3.0 x16

Memory Size: 2 GB GDDR5, 2000 MHz

Memory Interface: 128-bit Memory Bandwidth: 64 GB/s

Connectors 4mDP Outputs **Maximum Resolution** DisplayPort™ 1.4:

- up to 4x 5120 x 2880 x 24 bpp @ 60Hz - supports Multi-Stream Transport (MST)

Image Quality Features 10-bit internal display processing pipeline

10-bit scan-out support

Display Output 4 mDP Connectors

Shading Architecture Full Microsoft DirectX® 12 Shader Model 5.1

Supported Graphics APIs OpenGL® 4.5

DirectX® 12 Vulkan™ 1.0

API support includes:

CUDA C, CUDA C++, DirectCompute, OpenCL

Available Graphics

Drivers

Microsoft Windows 10 Microsoft Windows 8.1 Microsoft Windows 7

Linux®

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes

AMD FirePro™ W2100 2GB Graphics **Form Factor**

Low Profile, half length (full-height bracket included)

Graphics Controller

AMD FirePro™ W2100 professional graphics based on Oland GPU. GPU: 320 Stream Processors organized into 5 Compute Units

GPU Frequency: 630Mhz

Power: 26W Cooling: Active

Bus Type PCI Express® x8, Generation 3.0

Memory 2GB DDR3 memory

Memory Bandwidth: up to 28.8 GB/s

Memory Width: 128 bit

Connectors 2x Display Port™ 1.2 connectors

Factory Configured: No video cable adapter included After market option kit: No video cable adapter included

Additional DisplayPort-to-VGA or DisplayPort-to-DVI adapters are available as Factory Configuration or Option Kit accessories.

Technical Specifications - Graphics

Maximum Resolution DisplayPort™ 1.2:

- up to 4096x2160 x 24 bpp @ 60Hz

Dual Link DVI(I) (requires adapter cable): - up to 2560 x 1600 x 32 bpp @ 60Hz

Single Link-DVI(I)(requires adapter cable): - up to 1920 x 1200 x 32 bpp @ 60Hz

VGA (requires adapter cable):

- up to 1920 x 1200 x 32 bpp @ 60Hz

Image Quality Features Advanced support for 8-bit, 10-bit, and 16-bit per RGB color component.

High bandwidth scaler for high quality up and downscaling.

Display Output 2 x DisplayPort™ 1.2a

Maximum number of displays: 2

Shading Architecture Shader Model 5.0

Supported Graphics APIs OpenCL™ 1.2, DirectX® 11.2/12, OpenGL® 4.4

OpenGL® 4.4 support with driver release 14.301.xxx

OpenCL™ 1.2 conformance expected with drive release 14.301.xxx

Available Graphics

Drivers

Windows10 (64-bit and 32-bit) Windows 8.1 (64-bit and 32-bit) Windows 7 (64-bit and 32-bit)

Linux®

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes Depending on the card model, native DisplayPort™ connectors and/or

certified DisplayPort™ active or passive adapters to convert your monitor's native input to your card's DisplayPort™ or Mini-DisplayPort™ connector(s)

may be required. See www.amd.com/FirePro™ for details.

NVIDIA® Quadro® P1000 1st GFX 4GB Graphics

Form Factor

Dimensions: 2.713" H x 5.7" L Single Slot, Low Profile

Cooling: Active Weight: 129 grams

Graphics Controller NVIDIA® Quadro® P1000 Graphics Card

GP107-860 GPU

640 NVIDIA® CUDA® cores Max Power: 47 Watts

Bus Type PCI Express 3.0 x16

Memory Size: 4 GB GDDR5, 2500 MHz



Technical Specifications - Graphics

Memory Interface: 128-bit memory interface Memory Bandwidth: 80 GB/s memory bandwidth

4mDP Outputs

Maximum Resolution DisplayPort™ 1.4:

- up to 4x 5120 x 2880 x 24 bpp @ 60Hz - supports Multi-Stream Transport (MST)

Image Quality Features 10-bit internal display processing pipeline

10-bit scan-out support

Display Output 4 mDP Connectors

Shading Architecture Full Microsoft DirectX® 12 Shader Model 5.1

Supported Graphics APIs OpenGL® 4.5

DirectX® 12 Vulkan™ 1.0

API support includes:

CUDA C, CUDA C++, DirectCompute, OpenCL™

Available Graphics

Drivers

Connectors

Microsoft Windows 10 Microsoft Windows 8.1 Microsoft Windows 7

Linux®

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes

NVIDIA® Quadro® P2000 1st GFX 5GB Graphics **Form Factor** Dimensions: 4.4"Hx7.9"L

Single Slot Cooling: Active Weight: 260 grams

Graphics Controller NVIDIA® Quadro® P2000 Graphics Card

Power: 75 Watts

Bus Type PCI Express 3.0 x16 **Memory** Size: 5GB GDDR5

Memory Bandwidth: 140 GB/s

Memory Width: 160-bit

Connectors 4x DisplayPort™ 1.4

Factory Configured Option: No adapter included with card After Market Option: No video cable adapter included

Additional DVI to VGA, DisplayPort™ to VGA, DisplayPort™ to DVI, and DisplayPort™ to Dual-Link DVI adapters available as accessories.

Maximum Resolution DisplayPort™:

- up to 5120 x 2880 x 24 bpp @ 60Hz

- supports High Bit Rate 2 (HBR2) and Multi-Stream Transport (MST) DP 1.3

& 1.4 ready.

DL-DVI(I) output:

- up to 2560 x 1600 x 32 bpp @ 60 Hz



Technical Specifications - Graphics

Single Link-DVI(I) output:

- up to 1920 x 1200 x 32 bpp @ 60Hz

HDMI 2.0 (requires DP to HDMI adapter):

5120 x 2880 x 24 bpp @ 60Hz

Image Quality Features 12-bit internal display pipeline (hardware support for 12-bit scanout on

supported panels, applications and connection)

Stereoscopic 3D display support including NVIDIA® 3D Vision™ technology,

NVIDIA® Mosaic and nView.

Display Output Maximum number of displays

- 4 direct attached monitors

Maximum number of monitors across all available NVIDIA® Quadro® P2000

outputs is 4.

Shader Model 5.1

Shading Architecture

Supported Graphics APIs OpenGL® 4.5

DirectX® 12

API support includes:

CUDA C, CUDA C++, DirectCompute 5.0, OpenCL™, Java, Python, and Fortran

software

Available Graphics

Drivers

Microsoft Windows 10

Microsoft Windows 7 Professional 64bit

 $\text{Linux}^{\text{@}}$ - Full OpenGL $^{\text{@}}$ implementation, complete with NVIDIA $^{\text{@}}$ Quadro $^{\text{@}}$ and

ARB extensions

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes

Radeon™ Pro WX 3100 4GB Graphics **Form Factor**

Low-Profile Single Slot (6.6" Length)

Graphics Controller

Polaris12 GL

GPU: 512 Stream Processors organized into 8 Compute Units

Power: 50 Watts Cooling: Active

Memory 4GB GDDR5 memory

Memory Bandwidth: 6 Gbps / 96 GB/s

Memory Width: 128 bit

Connectors

2x Mini DisplayPort™ 1.4 plus 1x DisplayPort™ 1.4 – HDR ready connectors

with HBR3 and MST support.

Factory Configured: No adapters included

After market option kit: One mDP-to-DP cable adapters included

Technical Specifications - Graphics

Additional Mini DisplayPort™-to-DisplayPort™, DisplayPort™-to-VGA or DisplayPort™-to-DVI adapters are available as Factory Configuration or

Option Kit accessories.

Maximum Resolution

5K support @ 60Hz

• 1x single-cable 5K monitor, or 2x dual-cable 5K monitors

3x 4K support @ 60Hz

Image Quality Features

Advanced support for 8-bit and 10-bit per RGB color component. High

bandwidth scaler for high quality up and downscaling

Display Output

3 full physical DP1.3 HBR3 / DP1.4 HDR outputs

FreeSync support

GPU Architecture

Polaris

Supported Graphics APIs DirectX°12

OpenGL[®] 4.5 OpenCL[™] 2.0 Vulkan[™] 1.0

Available Graphics

Windows 10 64-bit

Drivers

(Windows® 7 64-bit available from AMD)

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes

- HDR content requires that the system be configured with a fully HDR-ready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windowed mode content requires operating system support.
- 2. AMD PowerTune and AMD ZeroCore Power are technologies offered by certain FirePro™ and Radeon™ Pro products, which are designed to intelligently manage GPU power consumption in response to certain GPU load conditions.
- 3. As of September 2016, certified for DisplayPort™ 1.4 HBR3 and ready for DisplayPort™ 1.4 HDR based on independent verification by DisplayPort™ testing authority. HDR content requires that the system be configured with a fully HDR-ready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windowed mode content requires operating system support.

Radeon™ Pro WX 4100 4GB Graphics Form Factor

Low-Profile Single Slot (6.6" Length)

Graphics Controller

Polaris 11 Baffin GL XT

GPU: 1024 Stream Processors organized into 16 Compute Units

Power: 50 Watts Cooling: Active

Memory

4GB GDDR5 memory

Memory Bandwidth: 6 Gbps / 96 GB/s

Technical Specifications - Graphics

Memory Width: 128 bit

Connectors 4x Mini DisplayPort™ 1.4 – HDR ready connectors with HBR3 and MST

support.

Factory Configured: Four mDP-to-DP cable adapters included After market option kit: Four mDP-to-DP cable adapters included

Additional DisplayPort-to-VGA or DisplayPort-to-DVI adapters are available as Factory Configuration or Option Kit accessories.

Maximum Resolution 5K support @ 60Hz

1x single-cable 5K monitor, or 2x dual-cable 5K monitors

4x 4K support @ 60Hz

Image Quality Features Advanced support for 8-bit and 10-bit per RGB color component. High

bandwidth scaler for high quality up and downscaling

Display Output 4 full physical DP1.3 HBR3 / DP1.4 HDR outputs

FreeSync support

GPU Architecture GCN 4th Generation

Supported Graphics APIs DirectX°12

OpenGL® 4.5 OpenCL™ 2.0 Vulkan™ 1.0

Available Graphics

Drivers

Windows 10 64-bit Windows® 7 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes

- 4. HDR content requires that the system be configured with a fully HDR-ready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windowed mode content requires operating system support.
- AMD PowerTune and AMD ZeroCore Power are technologies offered by certain FirePro[™] and Radeon[™] Pro products, which are designed to intelligently manage GPU power consumption in response to certain GPU load conditions.
- 6. As of September 2016, certified for DisplayPort™ 1.4 HBR3 and ready for DisplayPort™ 1.4 HDR based on independent verification by DisplayPort™ testing authority. HDR content requires that the system be configured with a fully HDR-ready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windows mode content requires operating system support.

Form Factor Dimensions: 4.4"H x 9.5"L

Technical Specifications - Graphics

NVIDIA® Quadro® P4000 1st GFX 8GB Graphics

Single-slot, full-height

Weight: 475 grams (without extender)

Graphics Controller NVIDIA® Quadro® P4000 Graphics Card

GPU: GP104 with 1792 CUDA cores

Power: 120 Watts

Bus Type PCI Express 3.0 x16
Memory Size: 8GB GDDR5

Memory Bandwidth: 243 GB/s Memory Width: 256-bit

Connectors 4 x DisplayPort 1.4

3-pin mini-DIN connector via optional bracket

1 x 6-pin auxiliary power connector 4-pin header for stereo signal SYNC connector for Quadro® Sync II

2 x SLI connectors

Factory Configured Option: No video cable adapter included After Market Option: No video cable adapter included

Additional DisplayPort-to-VGA, DisplayPort-to-HDMI, or DisplayPort-to-

DVI adapters are available as accessories

Maximum Resolution Dual-link internal TMDS (DVI 1.0):

- up to 2560 x 1600 x 32 bpp @ 60 Hz

Single-link internal TMDS (DVI 1.0): - up to 1920 x 1200 x 32 bpp @ 60 Hz

HDMI[™] 2.0b (requires DP to HDMI adapter): - up to 5120 x 2880 x 24 bpp @ 60Hz

DisplayPort:

up to 4096 x 2160 x 30 bpp @ 60Hz
 up to 2560 x 1600 x 30 bpp @ 120 Hz

- supports High Bit Rate 2 (HBR2) and Multi-Stream Transport (MST)

Using two DP outputs, the P4000 can drive one dual DP input display with

5120 x 2880 x 30 bpp @ 60Hz resolution.

Image Quality Features Advanced support for 8-bit, 10-bit, and 12-bit per RGB color

component.

HDCP 2.2 support over DisplayPort, DVI, and HDMI connectors

NVIDIA 3D Vision™ and other 3D stereo technologies

NVIDIA Mosaic and nView

Display Output Maximum number of displays

- 4 direct attached monitors

Maximum number of monitors across all available Quadro P4000 outputs

is 4.

Shading Architecture Shader Model 5.1



Technical Specifications - Graphics

Supported Graphics APIs OpenGL 4.5

DirectX 12 Vulcan 1.0

API support includes:

CUDA C, CUDA C++, DirectCompute 5.0, OpenCL, Java, Python, and Fortran

Available Graphics

Drivers

Microsoft Windows 10 Microsoft Windows 7

Linux® - Full OpenGL implementation, complete with NVIDIA and ARB

extensions

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes

Quadro P4000 offered as Factory Configured Option does not include a video cable adapter. Video cable adapters must be ordered separately.

2. Quadro P4000 offered as an After Market Option does not include video cables. Video cable adapters must be ordered separately.

NVIDIA® Quadro® P5000 Form Factor 1st GFX 16GB Graphics

Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 815 grams / 1.80 lbs

Graphics Controller

NVIDIA® Quadro® P5000 graphics

GPU: 2560 NVIDIA® CUDA® Parallel Processing Cores

Power: 180 Watts Cooling: Active

Memory

16GB GDDR5X memory

Memory Bandwidth: Up to 288 GB/s

Memory Width: 256 bit

ECC Memory (disabled by default)

Connectors

DP (x4) with HDR support

DL-DVI(D)

3-pin mini-DIN connector

SLI connector

NVIDIA® Quadro® Sync connector (compatible with NVIDIA® Quadro® II

Sync)

One 8-pin auxiliary power connector

Factory configured option: No video cable adapter included with card. After market option Kit: No video cable adaptor included with card.

DVI to VGA, DisplayPort™ to VGA, DisplayPort™ to DVI, and DisplayPort™ to

Dual-Link DVI adapters available as accessories.

Technical Specifications - Graphics

Maximum Resolution 5K support @ 60Hz

1x single-cable 5K monitor, or 2x dual-cable 5K monitors

Image Quality Features Advanced support for 8-bit, 10-bit, and 12-bit per RGB color

component.

HDCP 2.2 support over DisplayPort™, DVI, and HDMI

connectors

NVIDIA® 3D Vision™ and other 3D stereo technologies NVIDIA Mosaic and nView Desktop Management

Display Outputs¹ 4x DP1.4 HDR outputs (up to 3840x2160 UHD @ 120Hz refresh, or up to 8K

at 30Hz)

1x Dual-link DVI-D output (up to 2560 x 1600 @ 60 Hz and 1920x1200 @

120 Hz)

GPU Architecture NVIDIA Pascal™

Supported Graphics APIs DirectX[®]12, OpenGL[®] 4.5, OpenCL[™] 1.0, Vulkan[™] 1.0

Developer API support includes: CUDA C, CUDA C++, DirectCompute 5.0,

OpenCL™, Java, Python, and Fortran

Available Graphics

Drivers

Windows 10 64-bit Windows® 7 64-bit Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes 1- Supports up to a total of 4 displays

NVIDIA® Quadro® P6000 1st GFX 24GB Graphics **Form Factor** Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 967 grams / 2.14 lbs

Graphics Controller NVIDIA® Quadro® P6000 graphics

GPU: 3840 NVIDIA® CUDA® Parallel Processing Cores

Power: 250 Watts Cooling: Active

Memory 24GB GDDR5X memory

Memory Bandwidth: Up to 432 GB/s

Memory Width: 384 bit

ECC Memory (disabled by default)

Technical Specifications - Graphics

Connectors DP (x4) with HDR support

DL-DVI(I)

3-pin mini-DIN connector

SLI connector

Quadro Sync connector (compatible with Quadro II Sync)

One 8-pin auxiliary power connector

Factory configured option: No video cable adapter included with card. After market option Kit: No video cable adaptor included with card.

DVI to VGA, DisplayPort[™] to VGA, DisplayPort[™] to DVI, and DisplayPort[™]

to Dual-Link DVI adapters available as accessories.

Maximum Resolution 5K support @ 60Hz

1x single-cable 5K monitor, or 2x dual-cable 5K monitors

Image Quality Features Advanced support for 8-bit, 10-bit, and 12-bit per RGB color

component.

HDCP 2.2 support over DisplayPort, DVI, and HDMI connectors

NVIDIA 3D Vision™ and other 3D stereo technologies

NVIDIA Mosaic and nView

Display Outputs¹ 4x DP1.4 HDR outputs (up to 3840x2160 UHD @ 120Hz refresh, or up to 8K

at 30Hz)

1x Dual-link DVI-D output (up to 2560 x 1600 @ 60 Hz and 1920x1200 @

120 Hz)

GPU Architecture NVIDIA Pascal™

Supported Graphics APIs DirectX°12, OpenGL° 4.5, OpenCL™ 1.0, Vulkan™ 1.0

Developer API support includes: CUDA C, CUDA C++, DirectCompute 5.0,

OpenCL™, Java, Python, and Fortran

Available Graphics

Drivers

Windows® 10 64-bit Windows® 7 64-bit

Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes 1- Supports up to a total of 4 displays

Radeon™ Pro WX 7100 1st Form Factor GFX 8GB Graphics Graphics Graphics Graphics Core

Graphics Controller

Full-Height Single Slot (9.5" Length) Radeon™ Pro WX 7100 graphics

GPU: 2304 Stream Processors organized into 36 Compute Units

Power: 130 Watts Cooling: Active



Technical Specifications - Graphics

Memory 8GB GDDR5 memory

Memory Bandwidth: 7 Gbps / 224 GB/s

Memory Width: 256 bit

Connectors 4x Display Port 1.4 – HDR ready connectors with HBR3 and MST support.

Factory Configured: No video cable adapter included After market option kit: No video cable adapter included

Additional DisplayPort-to-VGA or DisplayPort-to-DVI adapters are available as Factory Configuration or Option Kit accessories.

Maximum Resolution 5K support @ 60Hz

1x single-cable 5K monitor, or 2x dual-cable 5K monitors

Image Quality Features Advanced support for 8-bit, 10-bit, and 16-bit per RGB color

component. High bandwidth scaler for high quality up and

downscaling

Display Output 4 full physical DP1.3 HBR3 / DP1.4 HDR outputs

FreeSync support

GPU Architecture GCN 4th Generation

Supported Graphics APIs DirectX°12

OpenGL® 4.5 OpenCL™ 2.0 Vulkan™ 1.0

Available Graphics

Drivers

Windows 10 64-bit Windows® 7 64-bit Linux® 64-bit

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

Notes

- HDR content requires that the system be configured with a fully HDR-ready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windowed mode content requires operating system support.
- 8. Radeon VR Ready Creator Products are select Radeon Pro and AMD FirePro™ GPUs that meet or exceed the Oculus Rift or HTC Vive recommended specifications for video cards/GPUs. Other hardware (including CPU) and system requirements recommended by Oculus Rift or HTC Vive should also be met in order to operate the applicable HMDs as intended. As VR technology, HMDs and other VR hardware and software evolve and/or become available, these criteria may change without notice.

Technical Specifications - Graphics

- AMD PowerTune and AMD ZeroCore Power are technologies offered by certain FirePro[™] and Radeon[™] Pro products, which are designed to intelligently manage GPU power consumption in response to certain GPU load conditions.
- 10. As of September 2016, certified for DisplayPort™ 1.4 HBR3 and ready for DisplayPort™ 1.4 HDR based on independent verification by DisplayPort™ testing authority. HDR content requires that the system be configured with a fully HDR-ready content chain, including: graphics card, monitor/TV, graphics driver and application. Video content must be graded in HDR and viewed with an HDR-ready player. Windowed mode content requires operating system support.

NVIDIA® Ouadro® Svnc II	Part number	1WT20AA

Dimensions (HxD) 6.0 inches × 4.2 inches

Devices Supported NVIDIA® Quadro® P4000
NVIDIA® Quadro® P5000
NVIDIA® Quadro® P6000

Bus Type Requires one free mechanical PCIe bus slot. 6-pin PCI or SATA power

connector

PCI Form Factor Full Height, half length, single slot

Ports 2 RJ45 connectors for carrying frame lock signals over CAT5 cables.

BNC Connector for external house synchronization.

Internal Connectors 6 NVIDIA SLI® style edge fingers for connection to compatible GPUs

Included with the board are 4 12-Inch Short Sync Cables to connect

to GPU's

Included with the board are 2 24-Inch Long Sync Cables to connect

to GPU's

System Requirements Requires one free mechanical PCIe bus slot. 6-pin PCI or SATA power

connector

Must be used with NVIDIA Quadro P4000, P5000 or P6000 graphics cards.

Requires Quadro driver version R375 or later.

Temperature - Operating 0° to 55° C

Temperature - Storage -40° to 60° C Relative Humidity - 10% to 80%

Operating

Power Requirements Board power dissipation: <15W

Operating Systems
Supported

Windows 10 64-bit Windows 7 64-bit

Linux® 64-bit

Kit Contents Contains:

Quadro Sync II Card

• 4 x 12-Inch Short Sync Cables

2 x 24-Inch Long Sync Cables (Two)

Quick Start Guide



Technical Specifications – Optical and Removable Storage

OPTICAL AND REMOVABLE STORAGE

HP 9.5mm Slim DVD Writer Description9.5mm height, tray-loadMounting OrientationEither horizontal or vertical

Interface Type SATA/ATAPI

Dimensions (WxHxD) 128 x 9.5 x 127mm

Supported Media Types DVD+R

DVD+RW DVD+R DL DVD-R DL DVD-R DVD-RW CD-R CD-RW

Disc Capacity DVD-ROM 8.5 GB DL or 4.7 GB standard

Full Stroke DVD < 200 ms (seek)
Full Stroke CD < 200 ms (seek)

Maximum Data Transfer Rates CD ROM Read CD-ROM, CD-R Up to 24X

CD-RW Up to 24X

DVD ROM Read DVD+RW Up to 8X

DVD-RW Up to 8X DVD+R DL Up to 8X DVD-R DL Up to 8X DVD-ROM Up to 8X DVD-ROM DL Up to 8X DVD+R Up to 8X DVD-R Up to 8X

Power Source SATA DC power receptacle

DC Power Requirements 5 VDC ± 5%-100 mV ripple p-p

DC Current 5 VDC -< 800 mA typical, <1600 mA

maximum

Operating Environmental Temperature 41° to 122° F (5° to 50° C)

(all conditions noncondensing)

Relative Humidity 10% to 80% Maximum Wet Bulb Temperature 84° F (29° C)

Operating Systems
Supported

Windows 10, Windows 7 Professional 32-bit and 64-bit,

Windows Vista Business 64*, Windows Vista Business 32*, Windows Vista Home Basic 32*, Windows 2000, Windows XP Professional or Windows XP

Home 32*.

Red Hat® Enterprise Linux® (RHEL) WS4**, 5, 6 Desktop/Workstation

SUSE Linux® Enterprise Desktop 10 & 11

* No driver is required for this device. Native support is provided by the

operating system.

Kit Contents HP SATA DVD Writer drive, installation guide.

Technical Specifications — Optical and Removable Storage

HP 9.5mm Slim DVD-ROM Description Drive

9.5mm height, tray-load **Mounting Orientation** Either horizontal or vertical

Interface Type SATA / ATAPI Dimensions (WxHxD) 128 x 9.5 x 127mm

Disc Capacity DVD-ROM Single layer: Up to 4.7 GB

Double layer: Up to 8.5 GB

Access Times DVD-ROM Single Layer < 110 ms (typical)

> CD-ROM Mode 1 < 110 ms (typical) Full Stroke DVD < 230 ms (typical) Full Stroke CD < 220 ms (typical)

Power Source SATA DC power receptacle

> **DC Power Requirements** 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC - <800mA typical, < 1600 mA

> > maximum

Operating Environmental Temperature

(all conditions noncondensing)

41° to 122° F (5° to 50° C)

Relative Humidity 10% to 80% Maximum Wet Bulb Temperature 84° F (29° C)

Operating Systems Supported

Windows 8.1, Windows 8 32-bit and 64-bit, Windows 7 Professional 32-bit

and 64-bit.

Windows Vista Business 64*, Windows Vista Business 32*, Windows Vista Home Basic 32*, Windows 2000, Windows XP Professional or Windows XP

Home 32*.

Red Hat® Enterprise Linux® (RHEL) WS4**, 5, 6 Desktop/Workstation

SUSE Linux® Enterprise Desktop 10 & 11

No driver is required for this device. Native support is provided by the

operating system.

Kit Contents 9.5mm Slim DVD-ROM Drive, 5.25" ODD Bay adapter/carrier, slim SATA

data/power cable, installation guide

HP 9.5mm Slim BDXL Blu- Description **Ray Writer**

9.5mm height, tray-load

Mounting Orientation

Either horizontal or vertical

Interface Type

SATA/ATAPI

Dimensions (WxHxD)

128 x 9.5 x 127mm

Supported Media Types

BD-ROM

BD-R

BD-RE DVD+R DVD+RW DVD+R DL DVD-R DL DVD-R DVD-RW CD-R



Technical Specifications – Optical and Removable Storage

CD-RW

DVD-ROM 8.5 GB DL or 4.7 GB standard **Disc Capacity**

> 25 GB (single-layer) Blu-ray 50 GB (dual-layer)

100/128 GB (BDXL)

Full Stroke DVD < 230 ms (seek) Full Stroke CD < 220 ms (seek)

< 230 ms (seek) (Full Stroke Blu-ray) Blu-ray

(Time to drive ready from tray Startup Time

loading)

BD-ROM (SL/DL) 255 / 285 BD-R (SL/DL) 255 / 285 BD-RE (SL/DL) **25S / 28S** DVD-ROM (SL/DL) 18S / 18S 255 / 255 DVD-R (SL/DL)

DVD-RW

DVD+R (SL/DL) **25S / 25S**

DVD+RW **25S** CD-ROM **15S**

Maximum Data Transfer CD ROM Read CD-ROM, CD-R Up to 24X

Rates

CD-RW Up to 24X DVD+RW Up to 8X

DVD ROM Read

DVD-RW Up to 8X DVD+R DL Up to 8X DVD-R DL Up to 8X DVD-ROM Up to 8X DVD-ROM DL Up to 8X DVD+R Up to 8X DVD-R Up to 8X

Blu-ray BD-ROM Up to 6X

BD-ROM DL Up to 6X BD-R Up to 6X BD-R DL Up to 6X BD-R Up to 6X BD-RE SL/DL Up to 6X

Power Source SATA DC power receptacle

> $5 \text{ VDC} \pm 5\%-100 \text{ mV ripple p-p}$ **DC Power Requirements DC Current** 5 VDC -900 mA typical, 2000mA

> > maximum

Operating Environmental Temperature

(all conditions noncondensing)

41° to 122° F (5° to 50° C)

Relative Humidity 10% to 80% Maximum Wet Bulb Temperature 84° F (29° C)

Operating Systems Supported

Windows 8.1, Windows 8 32-bit and 64-bit, Windows 7 Professional 32-bit

Windows Vista Business 64*, Windows Vista Business 32*, Windows Vista

Home Basic 32*, Windows 2000, Windows XP Professional or Windows XP Home 32*.



Technical Specifications — Optical and Removable Storage

Red Hat® Enterprise Linux® (RHEL) WS4**, 5, 6 Desktop/Workstation

SUSE Linux® Enterprise Desktop 10 & 11

No driver is required for this device. Native support is provided by the

operating system.

Kit Contents 9.5mm Slim BDXL Blu-Ray Writer, 5.25" ODD Bay adapter/carrier, slim

SATA data/power cable, installation guide

As Blu-ray is a new format containing new technologies, certain disc. digital connection, compatibility and/or performance issues may arise, and do not constitute defects in the product. Flawless playback on all systems is not guaranteed. In order for some Blu-ray titles to play, they may require a DVI or HDMI digital connection and your display may require HDCP support. HD-DVD movies cannot be played on this workstation.

HP SD Card Reader

Description Supports hardware ECC (Error Correction Code) function

Supports hardware CRC (Cyclic Redundancy Check) function

Supports SD 4-bit parallel transfer mode

Interface Type

USB 3.1 G1 High-speed interface

Dimensions (WxHxD) 1.15 x .9 x .15 in (29.00 x 23.6 x 3.15 mm) Fits conveniently in the Front IO

Bay

Supported Media Types Secure Digital Card (SD)

> Secure Digital High Capacity (SDHC) SD Extended Capacity Memory Card (SDXC)

SD Ultra High Speed II(SD UHSII)

These additional media types are supported with a card adapter.

Memory Stick Micro (M2)

miniSD

miniSD High Capacity

Micro SD Memory Card (MicroSD)

Micro SD High Capacity Memory Card (MicroSDHC)

Test Parameters/Conditions - Power applied, unit operating on system

±5%

Operating Systems

Supported

Windows 10

No driver is required for this device. Native support is provided by the

operating system.

Kit Contents SD card reader

Approvals USB-IF, WHQL, Compliant with USB Mass Storage Class Bulk only Transport

Specification Rev. 1.0.

Compliant Intel Front Panel I/O Connectivity Design Guide V. 1.3, FCC, CE,

BSMI, C-Tick, VCCI, MIC, cUL, TUVT

Weight 0.35 lbs. (0.16 kg)

Technical Specifications - Networking and Communications

NETWORKING AND COMMUNICATIONS

Integrated Intel I219 PCIe Connector GbE Controller

RJ-45 Controller

Intel I219 GbE platform LAN connect networking controller

Data Rates Supported 10/100/1000 Mbps

Boot ROM Support PXE, UEFI

Connect Speed LED Indicators

Off = No link

Link/Activity LED

Blinking = Activity

Speed LED

Off = 10Mbps

Amber = 100Mbps

Green = 1000Mbps

Management Capabilities Wake-On-LAN, Intel® Active Management Technology™ (AMT) 11.

NOTE: Intel[®] AMT[™] is not available on Intel Core X configs.

Integrated Intel I210 (not available on Intel Core X configs)

Connector **RJ-45** Intel® I210 Controller

10/100/1000 Mbps **Data Rates Supported**

Boot ROM Support PXE. UEFI **Connect Speed LED**

Indicators

Link/Activity LED

Off = No link

Blinking = Activity

Speed LED

Off = 10Mbps

Amber = 100Mbps

Green = 1000Mbps

Management Capabilities Wake-On-LAN

Intel® I210-T1

Networking Interface RJ-45

System Interface PCI Express 2.1 x1

Networking Speeds

Supported

10Mbps, 100Mbps, 1Gbps

Cabling (up to 100m) Cat3 (or higher) for 10Mbps

> Cat5 (or higher) for 100Mbps Cat5e (or higher) for 1Gbps

Length: 6.7cm (2.64 inches)

Power Consumption (active-typical)

0.81W

Physical Dimensions

(Bracket) Width: 1.8cm (0.709 inches)

Full-height end bracket: 12.07cm (4.755 inches) Low-profile end bracket: 8cm (3.15 inches)



Technical Specifications - Networking and Communications

Connect Speed LED Indicators

Link/Activity LED

- Off = No link
- Blinking = Activity

Speed LED

- Off = 10Mbps
- Green = 100Mbps
- Amber = 1Gbps

Operating Temperature

0 °C to 55 °C (32 °F to 131 °F)

Hardware Certifications

USA: FCC B, EU: UL CE. Japan: VCCI, Taiwan: BSMI,

Australia/New Zealand: CTICK,

Korea: KCC,

Canada: ICES-003/NMB-003

Intel® 1350-T2

Networking Interface

2 x RJ-45

System Interface

PCI Express 2.1 x4

Networking Speeds Supported

10Mbps, 100Mbps, 1Gbps

Cabling (up to 100m)

Cat3 (or higher) for 10Mbps Cat5 (or higher) for 100Mbps

Cat5e (or higher) for 1Gbps

Power Consumption

(active-typical)

4.4W

Physical Dimensions Length: 13.54cm (5.33 inches)

Width: 6.89 (2.71 inches)

Full-height end bracket: 12.0cm (4.725 inches) Low-profile end bracket: 7.92cm (3.117 inches)

Connect Speed LED Indicators

Link/Activity LED

Off = No link

Blinking = Activity

Speed LED

Off = 10Mbps

Green = 100Mbps

Amber = 1Gbps

Operating Temperature

0 °C to 55 °C (32 °F to 131 °F)

Hardware Certifications USA: FCC B.

EU: UL CE, Japan: VCCI, Taiwan: BSMI,

Australia/New Zealand: CTICK,

Korea: KCC.

Canada: ICES-003/NMB-003

Intel® 1350-T4

Networking Interface

4 x RJ-45

Technical Specifications - Networking and Communications

System Interface

Networking Speeds

Supported

10Mbps, 100Mbps, 1Gbps

PCI Express 2.1 x4

Cabling (up to 100m) Cat3 (or higher) for 10Mbps

> Cat5 (or higher) for 100Mbps Cat5e (or higher) for 1Gbps

Power Consumption (active-typical)

Physical Dimensions

Length: 13.54cm (5.33 inches)

Width: 6.89 (2.71 inches)

Full-height end bracket: 12.0cm (4.725 inches) Low-profile end bracket: 7.92cm (3.117 inches)

Connect Speed LED Indicators

Link/Activity LED Off = No link

Blinking = Activity

Speed LED

Off = 10MbpsGreen = 100Mbps

Amber = 1Gbps

0 °C to 55 °C (32 °F to 131 °F)

Operating Temperature

Hardware Certifications USA: FCC B.

> EU: UL CE. Japan: VCCI. Taiwan: BSMI,

Australia/New Zealand: CTICK,

Korea: KCC.

Canada: ICES-003/NMB-003

Intel® X550-T2

Networking Interface

2 x RJ-45 PCI Express 3 x4

System Interface

Networking Speeds

Supported

100Mbps, 1Gbps, 2.5Gbps, 5Gbps, 10Gbps

Cabling (up to 100m) Cat5 (or higher) for 100Mbps

Cat5e (or higher) for 1Gbps, 2.5Gbps, or 5Gbps

Cat6a (or higher) for 10Gbps

Power Consumption (active-typical)

3.9W at 100Mbps 5.5W at 1Gbps 11.2W at 10Gbps

Physical Dimensions

5.2 in x 2.7 in (without bracket)

Connect Speed LED

Link/Activity LED

Indicators

Off = No link

Blinking = Activity

Speed LED

Off = No link

Amber = <10Gbps

Green = 10Gbps

Technical Specifications - Networking and Communications

Operating Temperature

0 °C to 55 °C (32 °F to 131 °F)

Hardware Certifications

USA: FCC B, EU: UL CE, Japan: VCCI, Taiwan: BSMI,

Australia/New Zealand: CTICK,

Korea: KCC.

Canada: ICES-003/NMB-003

Intel® X710-DA2 10GBASE-SR Converged Network Adapter Networking Interface
System Interface

2 SFP+ Ports for LC SFP+ Transceivers

LC fiber optic cabling with LC SFP+ Transceivers

PCI Express 3.0 x8

Networking Speeds

Supported **Supported**

1Gbps, 10Gbps

Cabling
Power Consumption

(active-typical)

4.3W

Physical Dimensions Connect Speed LED

Indicators

6.578 in x 2.703 in Link/Activity LED

• Off = No link

• Blinking = Activity

Speed LED

Off = 10Mbps

Green = 100Mbps

• Amber = 1Gbps

Operating Temperature

0 °C to 55 °C (32 °F to 131 °F)

Hardware Certifications USA: FCC B,

EU: UL CE, Japan: VCCI, Taiwan: BSMI,

Australia/New Zealand: CTICK,

Korea: KCC,

Canada: ICES-003/NMB-003

10GbE SFP+ SR Transceiver **Connector Type** LC

Cable Type 62.5/125um or 50/125um (core/cladding), graded-index, low metal

content, multimode fiber optic, complying with ITU-T G.651 and ISO/IEC

793-2 Type A1b or A1a, respectively.

Cable Length 2-300m Wavelength 850nm Form Factor SFP+

Physical Dimensions $0.47(h) \times 0.54(w) \times 2.19(d)$ inches

(1.19 x 1.38 x 5.57 cm)

Operating Temperature OC to 45C (32F to 113F)
Operating Humidity 0% to 85%, noncondensing

Technical Specifications - Networking and Communications

Intel® 8265 WLAN Networking Speeds 802.11ac MU-MIMO (up to 867 Mbps)

Bluetooth 4.2

IEEE WLAN Standard IEEE 802.11a/b/g/n/ac, 802.11d, 802.11e, 802.11h, 802.11i, 802.11w;

802.11r, 802.11k, 802.11v pending

Bluetooth 4.2

System Interface PCI Express 2.1 x1

Antenna 2x2



Summary of Changes

SUMMARY OF CHANGES

Date of change:	Version History:		Description of change:
November 1, 2017 From v1 to v2 Added		Added	HP DisplayPort to HDMI Adapter, NVIDIA SLI 2-slot Graphics Connector and NVIDIA Quadro Sync II to Graphics section
		Changed	Graphics, Storage / Hard Drives and Memory sections, changed Front and internal view info on the Overview section, changed Operating Systems section, changed System Board section, changed System Configuration, DECLARED NOISE EMISSIONS and Physical Security and Serviceability sections
November 29, 2017	From v2 to v3	Added	Processors, hard drives and graphics to offerings, added Intel Xeon W-2195 to Processors section
		Changed	Wattage links on power supply section updated and Voltage links on efficientcy section updated
February 5, 2018	From v3 to v4	Added	Features and Supported Configurations for Intel® Core™ X- Series Processor Family
		Changed	Formatting



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